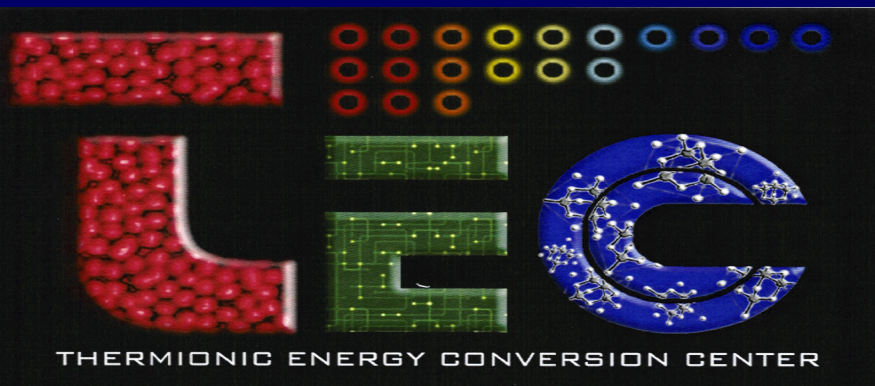


Nanoscale Opto Thermo Electric Energy Conversion Devices

Ali Shakouri

Director, Thermionic Energy Conv. Center
Baskin School of Engineering
University of California Santa Cruz



Acknowledgement: ONR MURI

(Dr. Mihal Gross)

UCSC (Schmidt), Berkeley
(Majumdar), **Harvard**
(Narayanamurti), **MIT (Ram),**
ASU (Nemanich), NCSU (Sitar),
Purdue (Sands), UCSB
(Bowers, Gossard, Stemmer)

Purdue University; 9 May 2008

Outline

AS 4/28/2008

Introduction/ Motivation

- Mutual interaction of heat, light and electricity in nanoscale devices

Micro Refrigerators on a Chip

Thermoreflectance Imaging

Thermal Runaway in Electroabsorption
Modulators

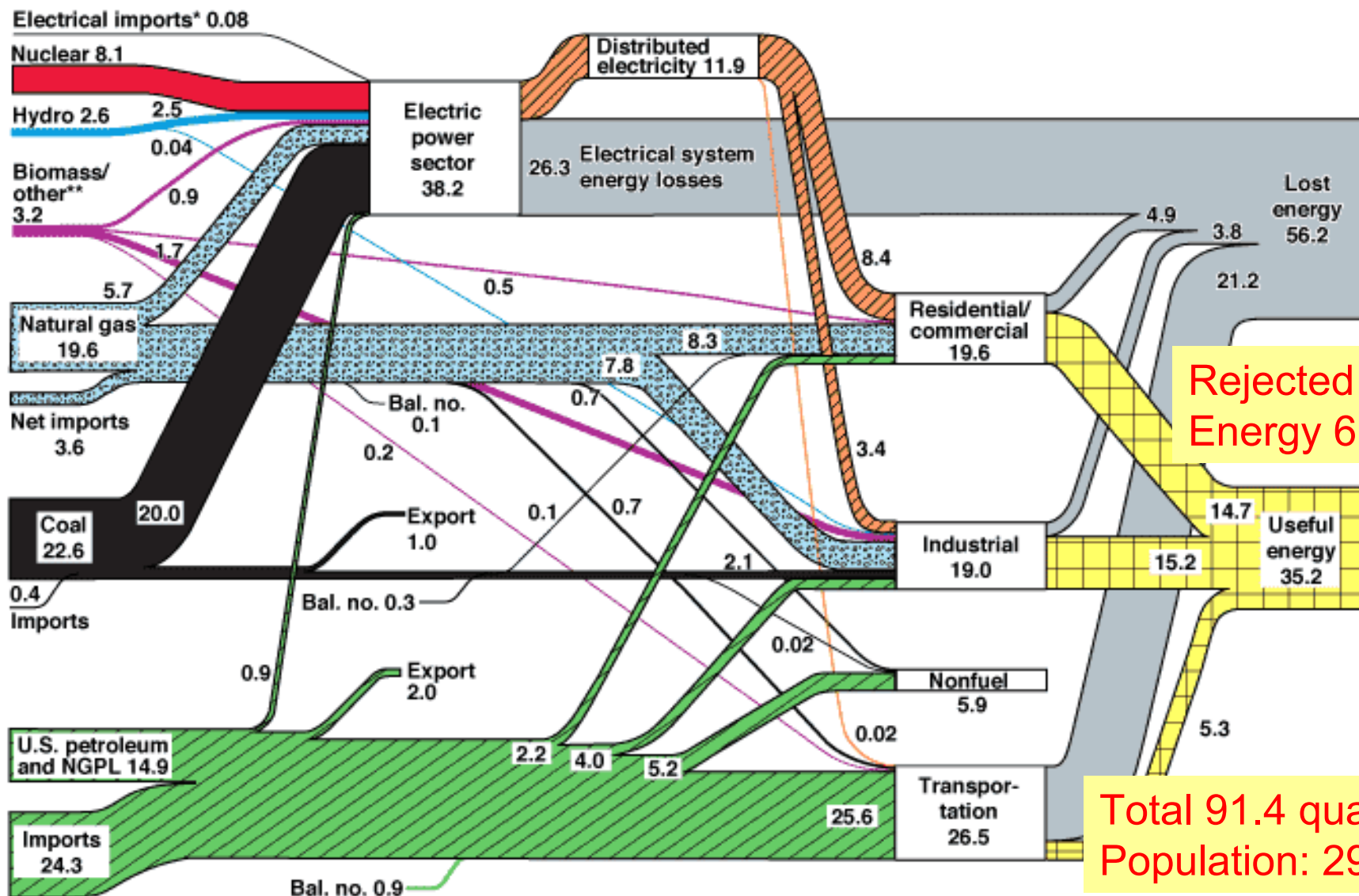
Thermionic Energy Conversion Center
Internally Cooled Devices

U.S. Energy Flow Trends – 2002

Net Primary Resource Consumption ~97 Quads



1/28/2008



Source: Production and end-use data from Energy Information Administration, *Annual Energy Review 2002*.

*Net fossil-fuel electrical imports.

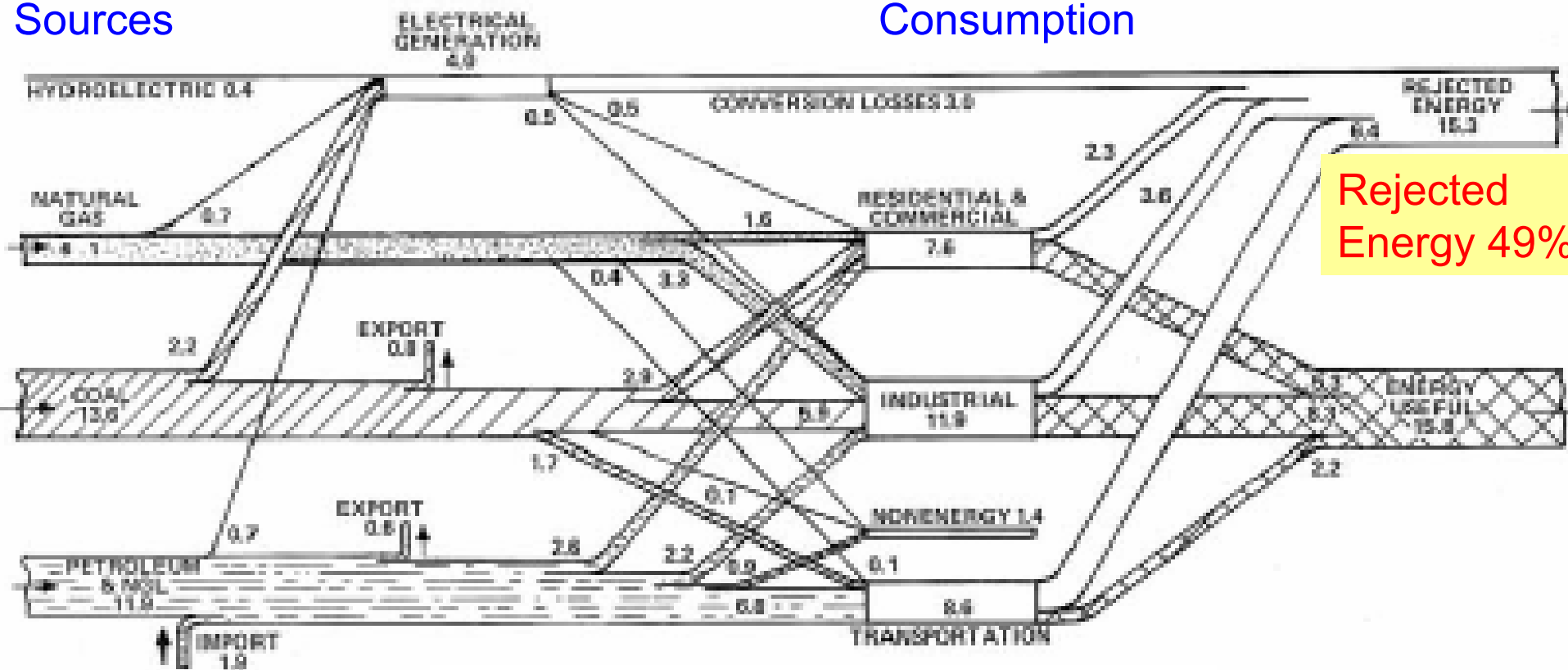
**Biomass/other includes wood, waste, alcohol, geothermal, solar, and wind.

June 2004
Lawrence Livermore
National Laboratory
<http://eed.llnl.gov/flow>

US Energy Flow 1950

Energy
Sources

Energy
Consumption



Rejected
Energy 49%

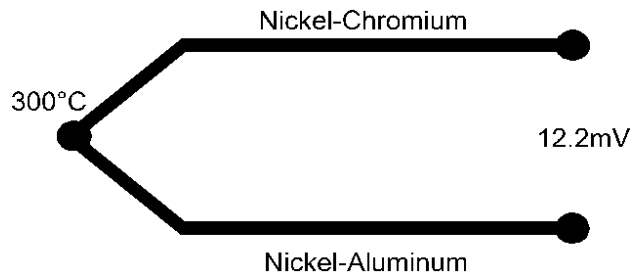
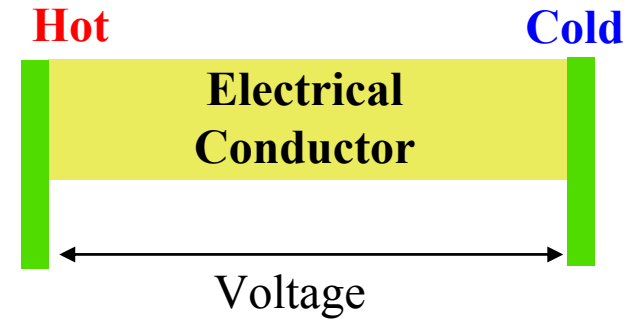
LLNL

Total 31.8 Quad
Population: 161M

Seebeck Effect (1821)

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Seebeck: $S = \frac{\Delta V}{\Delta T}$

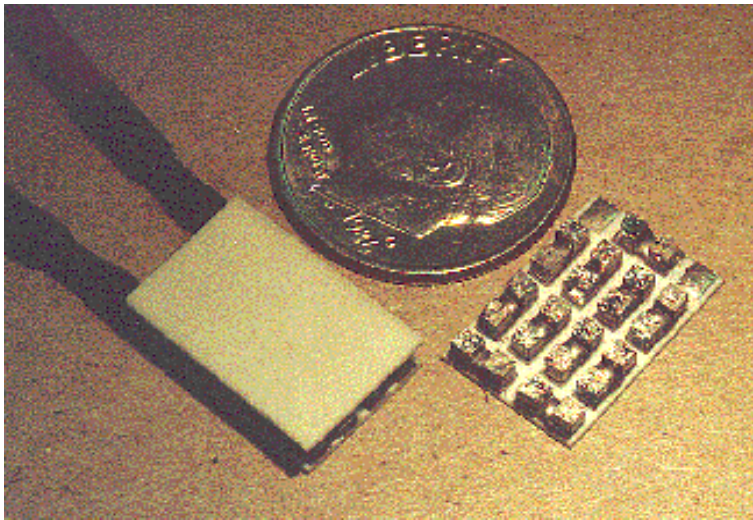
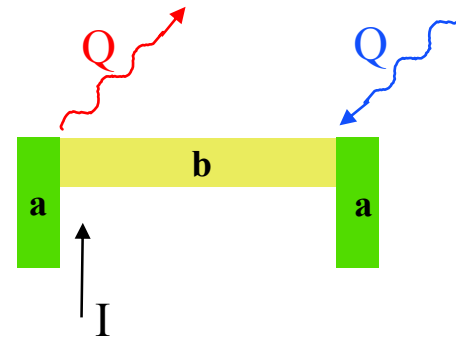


Temperature difference between two junctions can produce a voltage

Peltier Effect (1834)

Peltier:

$$\pi_{ab} = \pi_a - \pi_b = \frac{Q}{I}$$

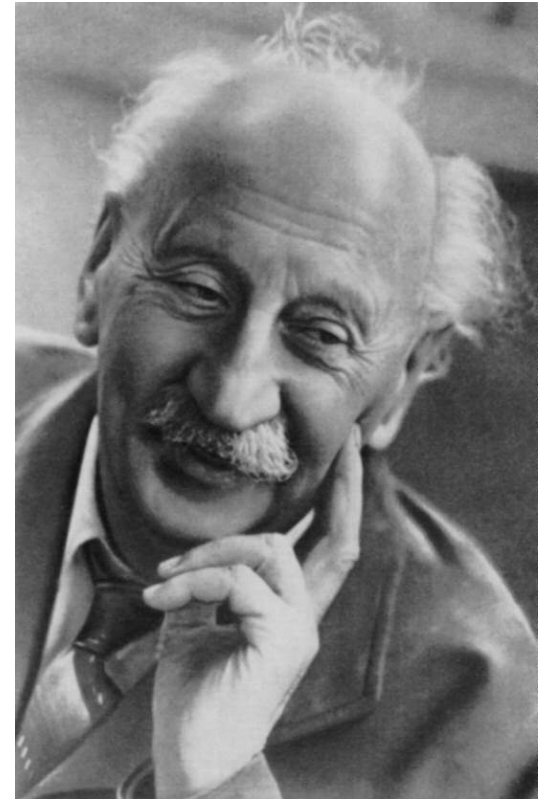


Commercial TE Module

- $\Delta T = 72^\circ\text{C}$ (no heat load)
- Cooling density $< 10\text{W}/\text{cm}^2$
- Efficiency 6-8% of Carnot

When the current flows from material (a) into material (b) and then back to material (a), it **heats** the first junction and **cools** the second one (or vice versa). Thus, heat is transferred from one junction to the other one.

- First practical devices USSR during WWII
 - Tens of thousands built, to power radios from any available heat source.
- In the 1950s-60s many in the US & USSR felt semiconductor thermoelectrics could replace mechanical engines, much as semiconductor electronics were replacing vacuum tube technology.
 - Hint: it didn't happen!

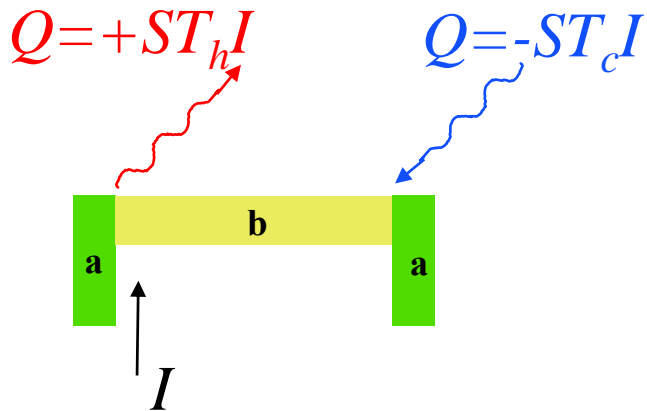


Abram F. Ioffe 1880-1960

Ioffe, A. F. (1957). Semiconductor Thermoelements and Thermoelectric Cooling. London, Infosearch Limited.

Efficiency of Thermoelectric Devices

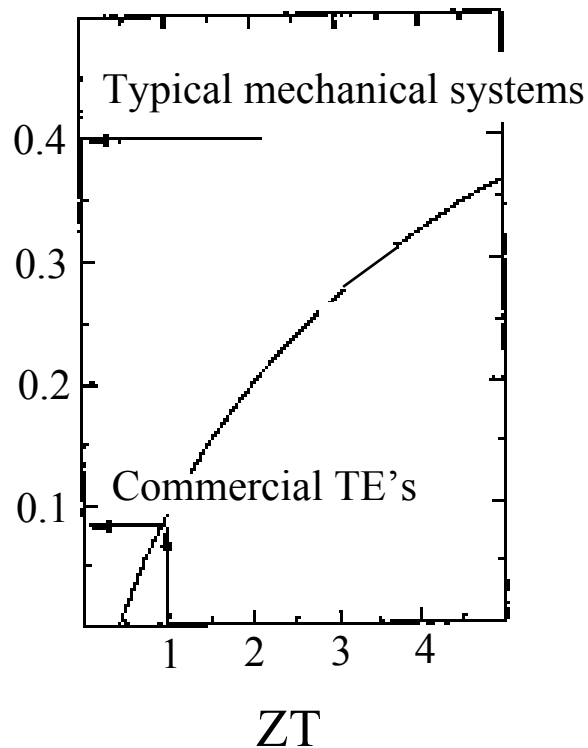
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$$Z = \frac{S^2 \sigma}{\beta}$$

$$Z = \frac{(\text{Seebeck})^2 (\text{electrical conductivity})}{(\text{thermal conductivity})}$$

Relative
Efficiency



- Melcor, Marlow and many other TE manufacturers provide coolers specifically designed for Telecom laser-cooling applications



Typical Distributed Feedback Laser:

$\Delta\lambda/\Delta T = \underline{0.1 \text{ nm}/^\circ\text{C}}$

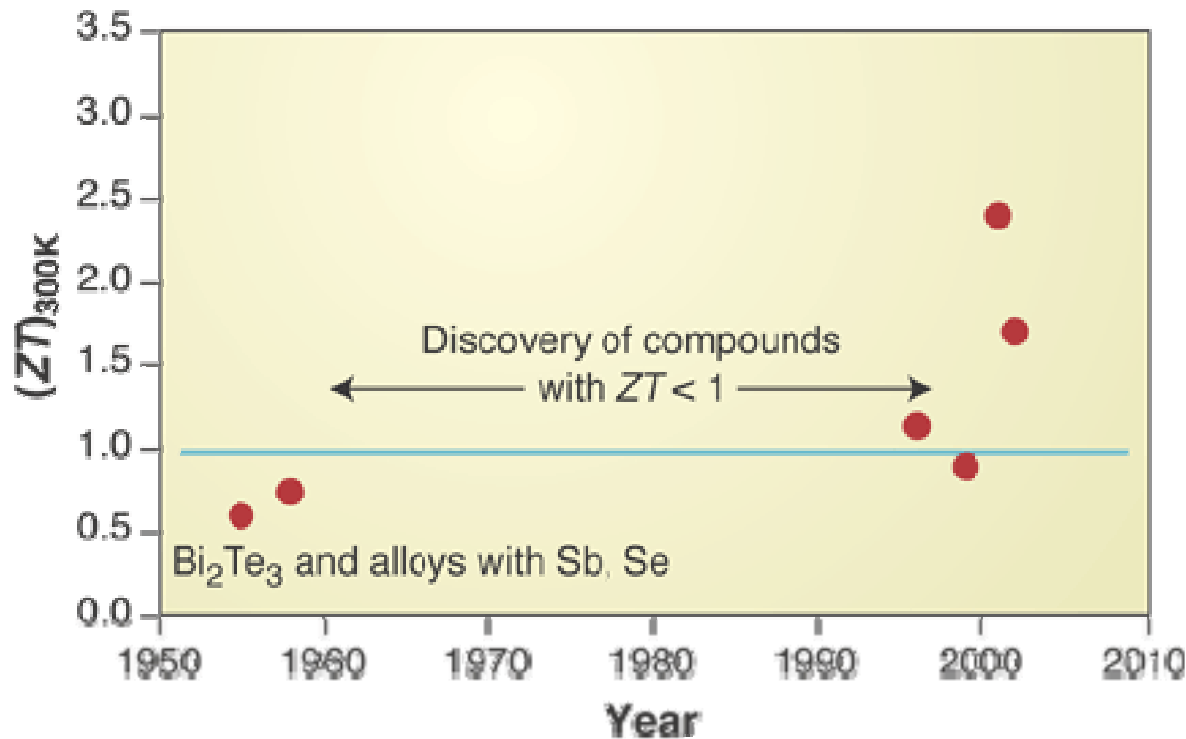
Heat generation kW/cm²



Cronin Vining, ZT Services

Recent Advances in Thermoelectrics

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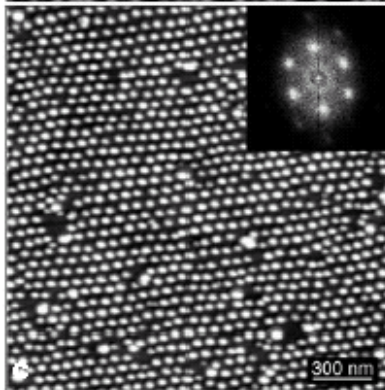
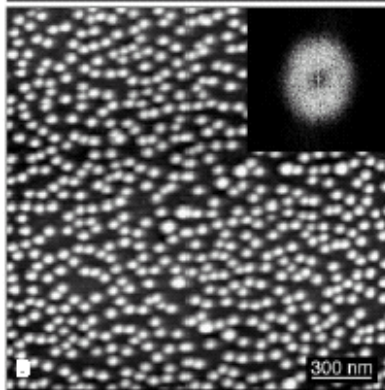
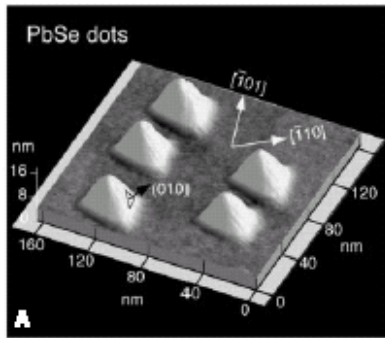
- Recent advances in nanostructured thermoelectric materials led to a sudden increase in $(ZT)_{300K} > 1$

A. Majumdar, *Science* 303, 777 (2004)

Superlattices/ Quantum Dot Thermoelectrics

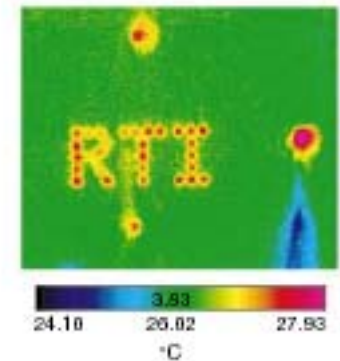
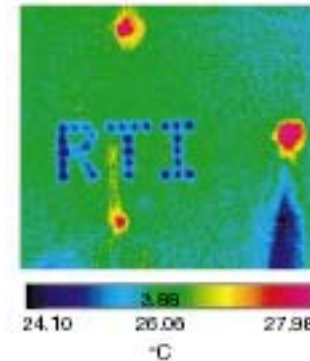
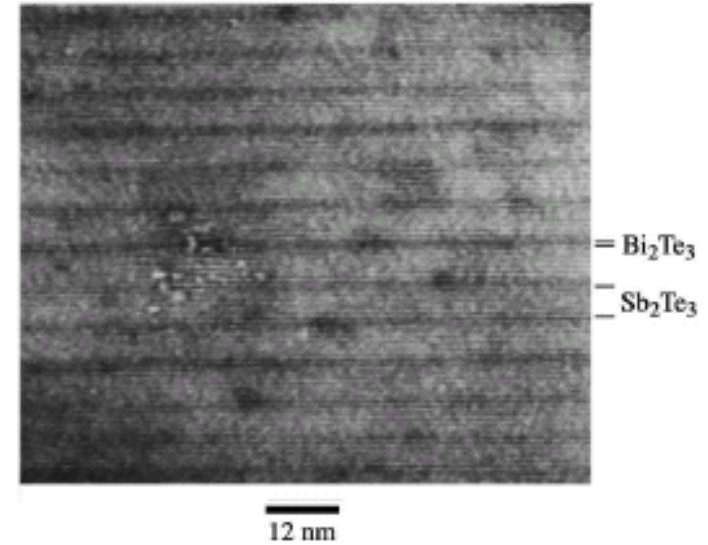
Harman (2002) and Venkatasubramanian (2001)

AS 4/28/2008



**PbTe/PbTeSe
Quantum Dot
Superlattices**

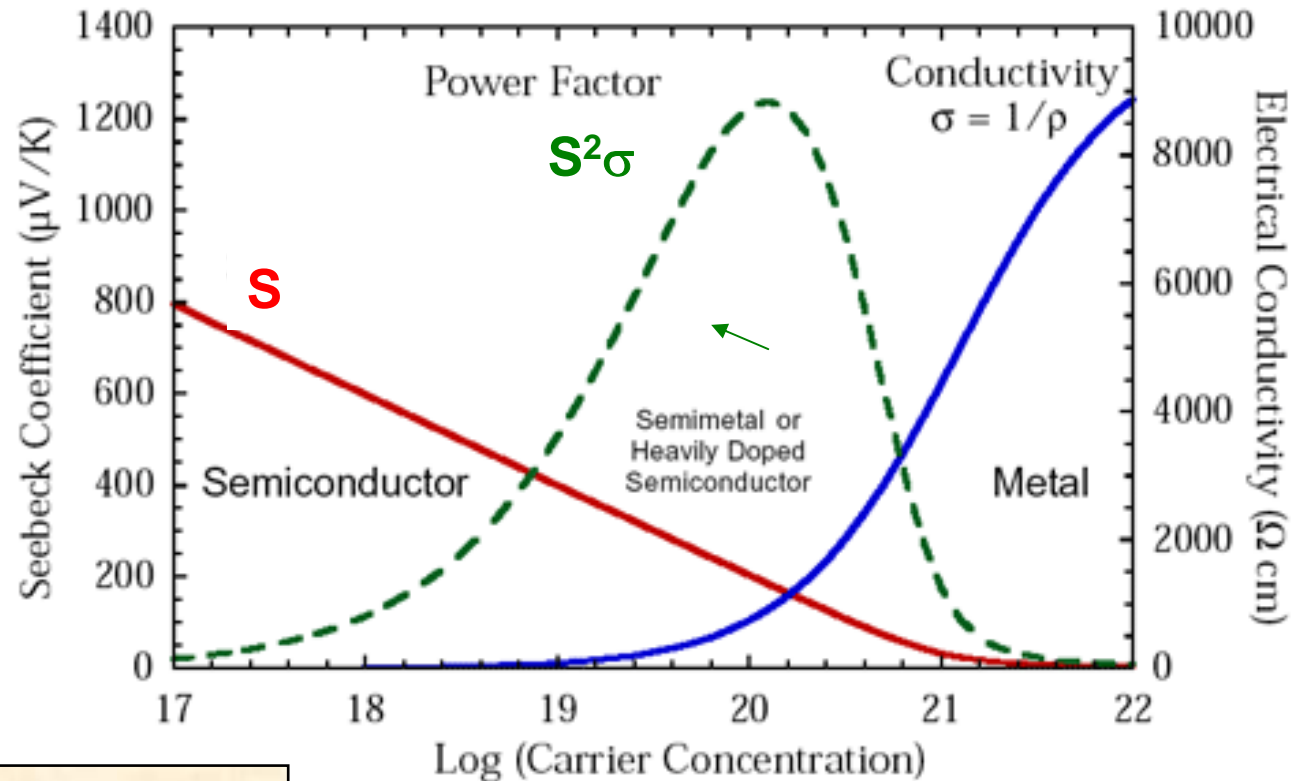
**ZT=2
T.C. Harman,
Science, 2002**



**$\Delta T=32.2$ K, ZT ~2-2.4
R. Venkatasubramanian, Nature, 2001**

Best thermoelectrics Materials

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$$Z = \frac{S^2 \sigma}{k}$$

$$Z = \frac{(\text{Seebeck})^2 (\text{electrical conductivity})}{(\text{thermal conductivity})}$$

J. Snyder (2003)

http://www.its.caltech.edu/~jsnyder/thermoelectrics/science_page.htm

For almost all materials, if doping is increased, electrical conductivity increases but Seebeck coefficient is reduced. Similarly $\sigma \leftrightarrow \kappa$

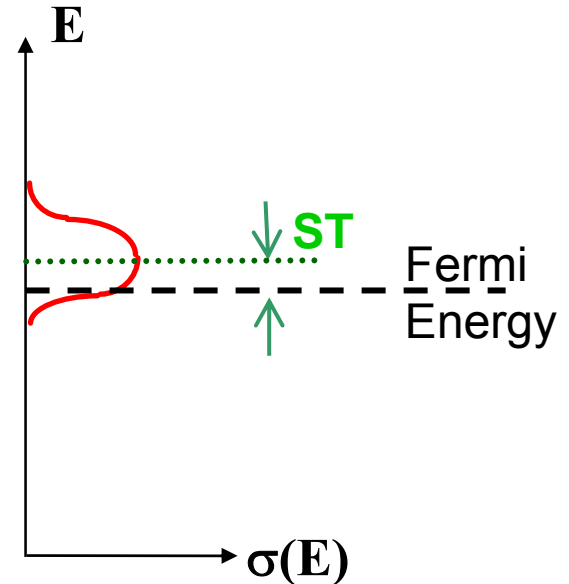
Differential Conductivity

Figure-of-Merit

$$Z = \frac{S^2 \sigma}{k_e + k_L}$$

$$Z = \frac{(\text{Seebeck})^2 (\text{electrical conductivity})}{(\text{thermal conductivity})}$$

$$\left\{ \begin{array}{l} \sigma = \int \sigma(E) dE \\ S = \frac{1}{eT} \frac{\int \sigma(E) (E - E_F) dE}{\int \sigma(E) dE} \propto \langle (E - E_f) \rangle \\ k_e = \text{function of } \langle (E - E_f)^2 \rangle \end{array} \right.$$

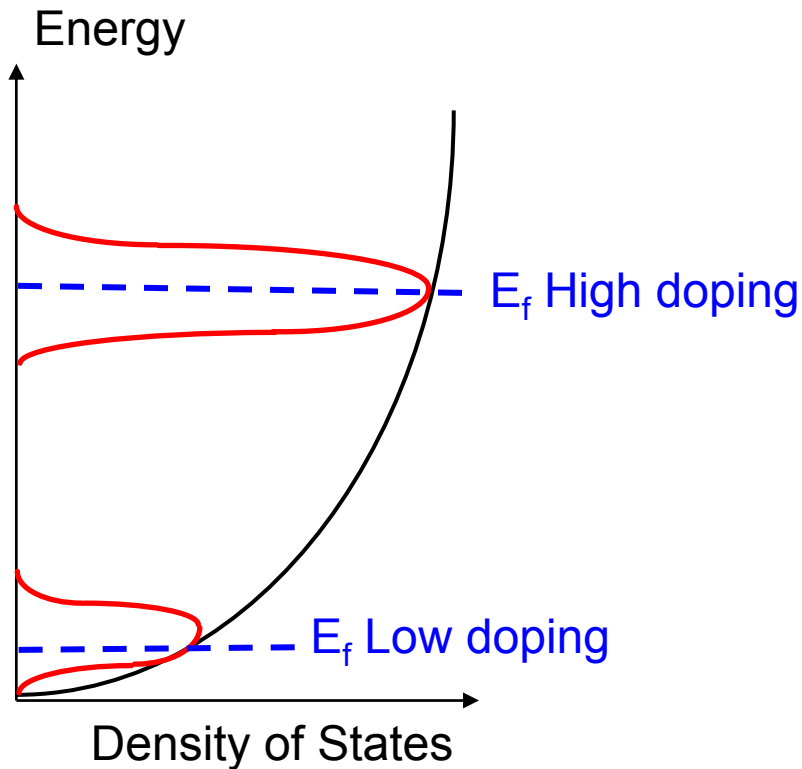


$$\sigma(E) \cong e^2 \tau(E) \bar{v}_x^2(E) \bar{n}(E) \left(-\frac{\mathcal{J}_{eq}}{\mathcal{E}} \right)$$

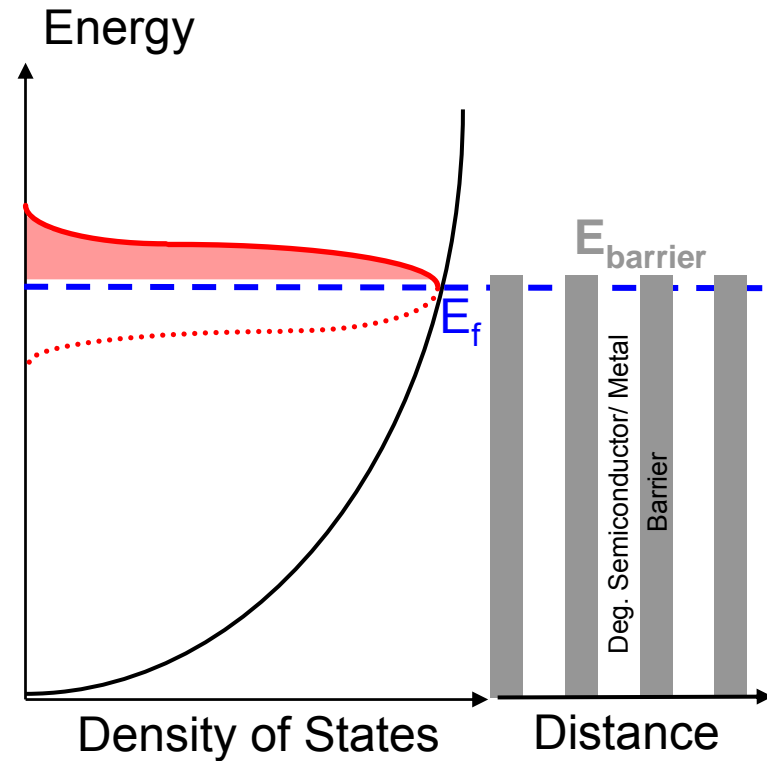
Differential Conductivity is a function of **relaxation time**, **group velocity** and **density-of-states**

Seebeck –Conductivity Trade off

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Doped Bulk Semiconductor

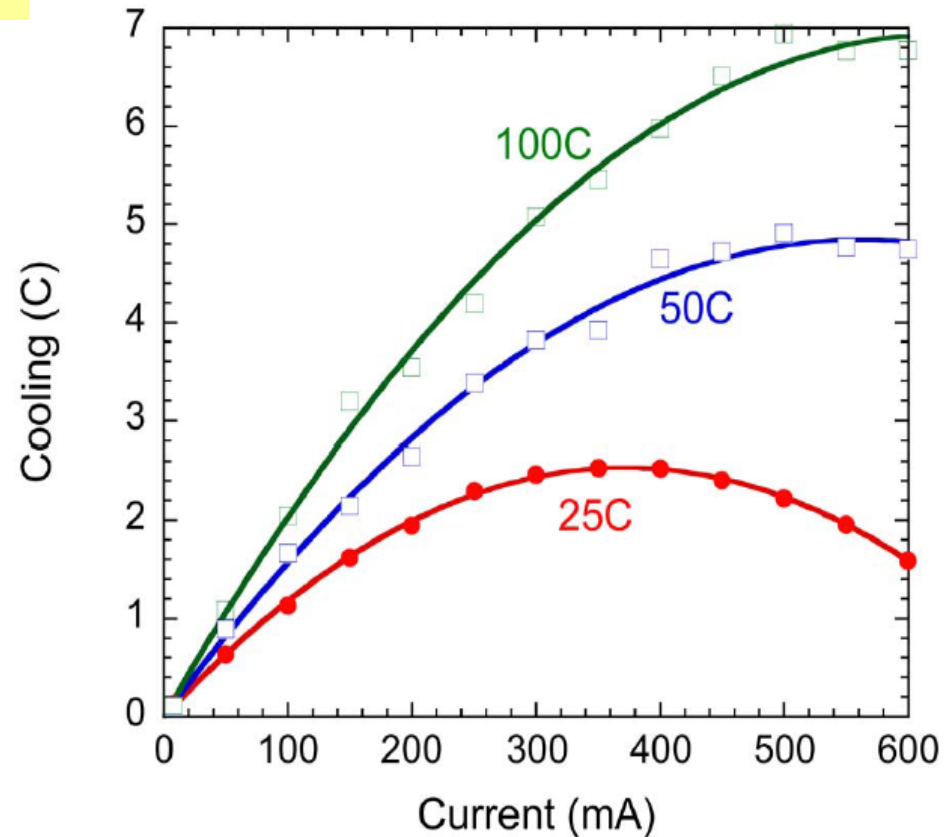
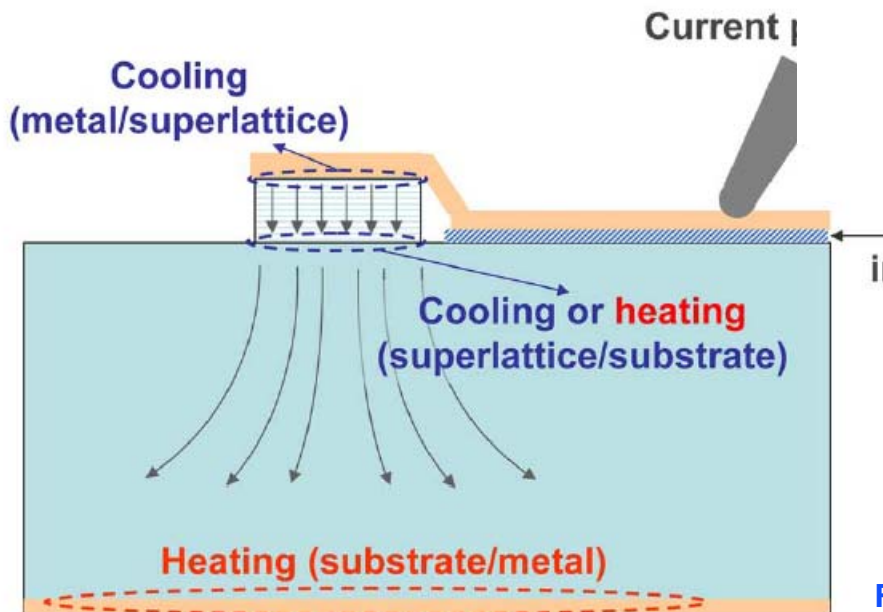
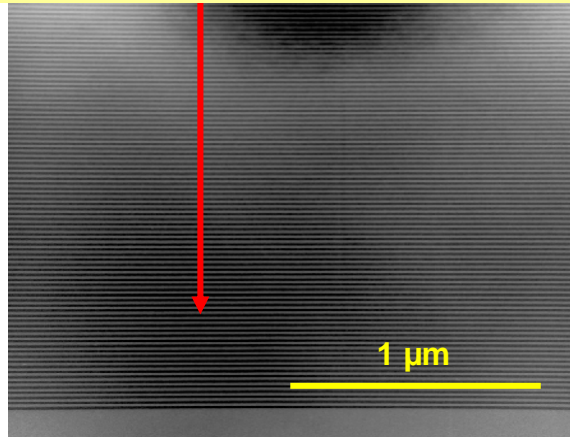


Deg. Semiconductor/Metal + Energy Filter (barriers)

Symmetry of DOS near Fermi energy is the main factor determining Seebeck coefficient.

Microrefrigerators on a chip

- Monolithic integration on silicon
- $\Delta T_{\max} \sim 4\text{C}$ at room temp. (7C at 100C)

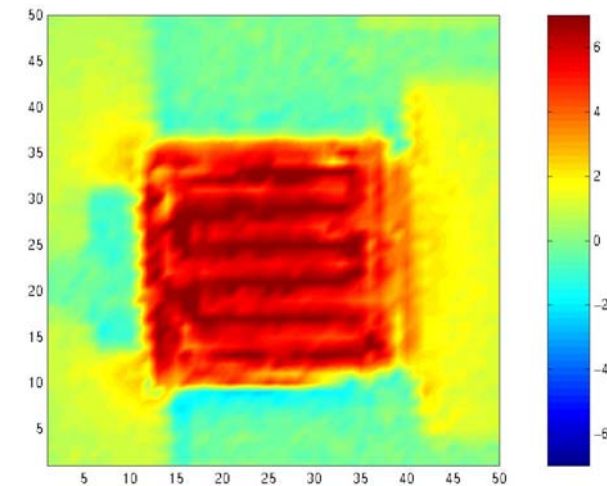
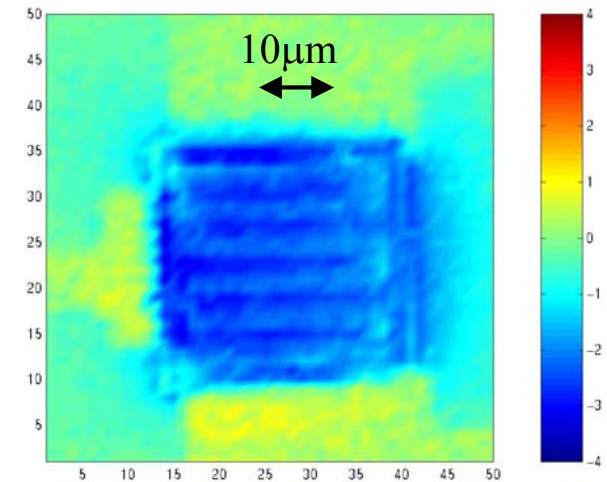
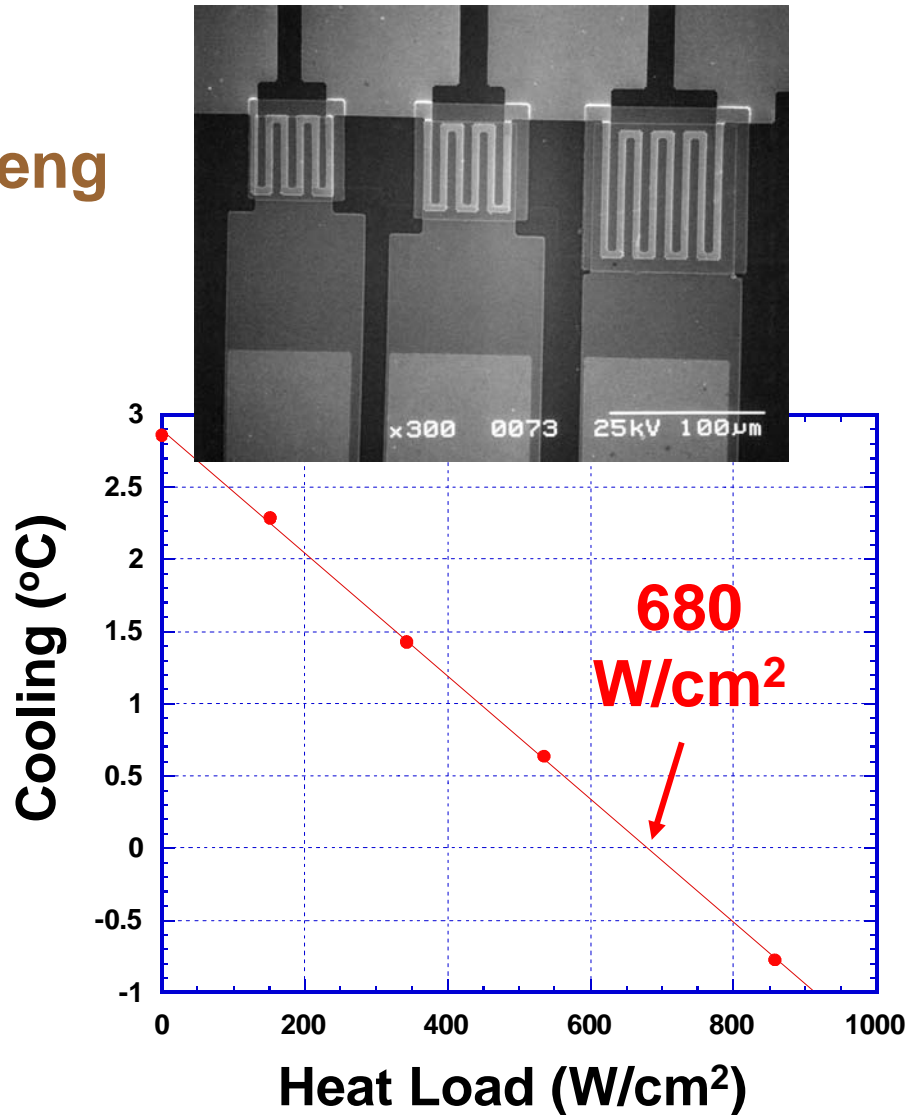


Nanoscale heat transport and microrefrigerators on a chip; A. Shakouri, **Proceedings of IEEE**, July 2006

Featured in Nature Science Update, Physics Today, AIP April 2001

Micro Refrigerator Integrated with Thin Film Heater

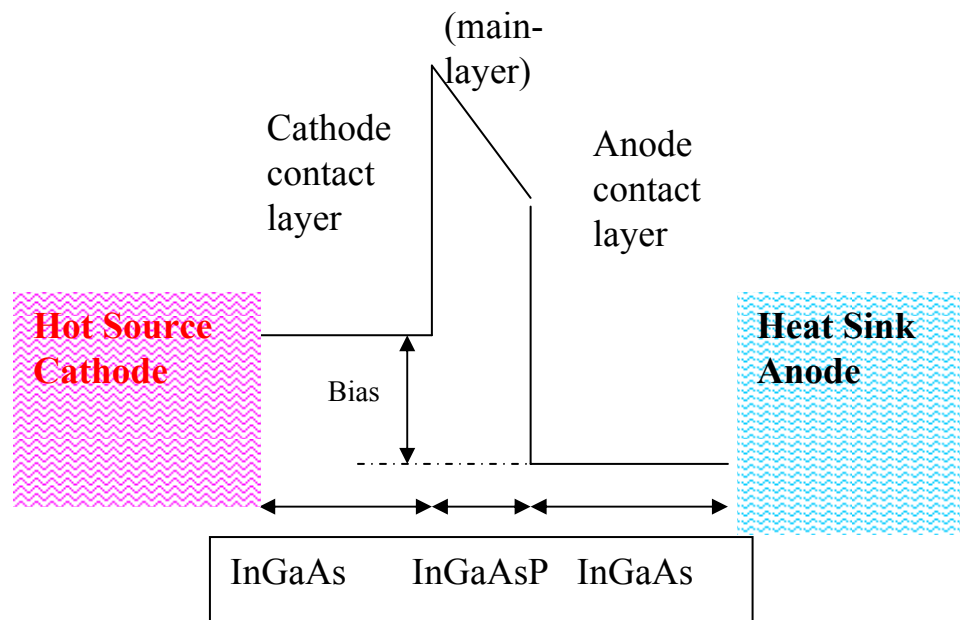
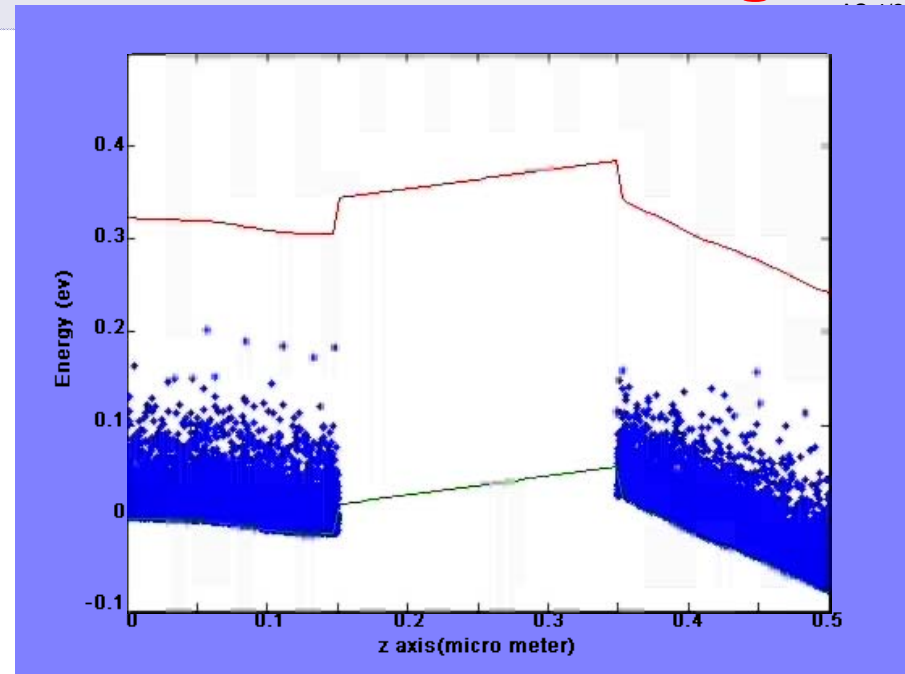
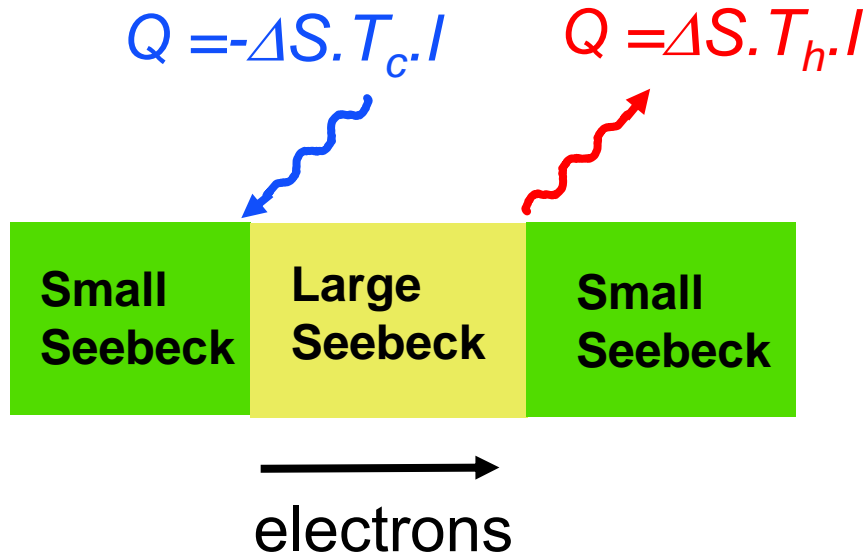
G. Zeng



G. Zeng, X. Fan, C. LaBounty, J.E. Bowers, E.Croke, J. Christofferson, D. Vashaee, A. Shakouri, "Direct Measurement of Cooling Power Density for Thin Film Supperlattice Micro Coolers," MRS Fall 2003.

Monte Carlo simulation of TE/TI cooling

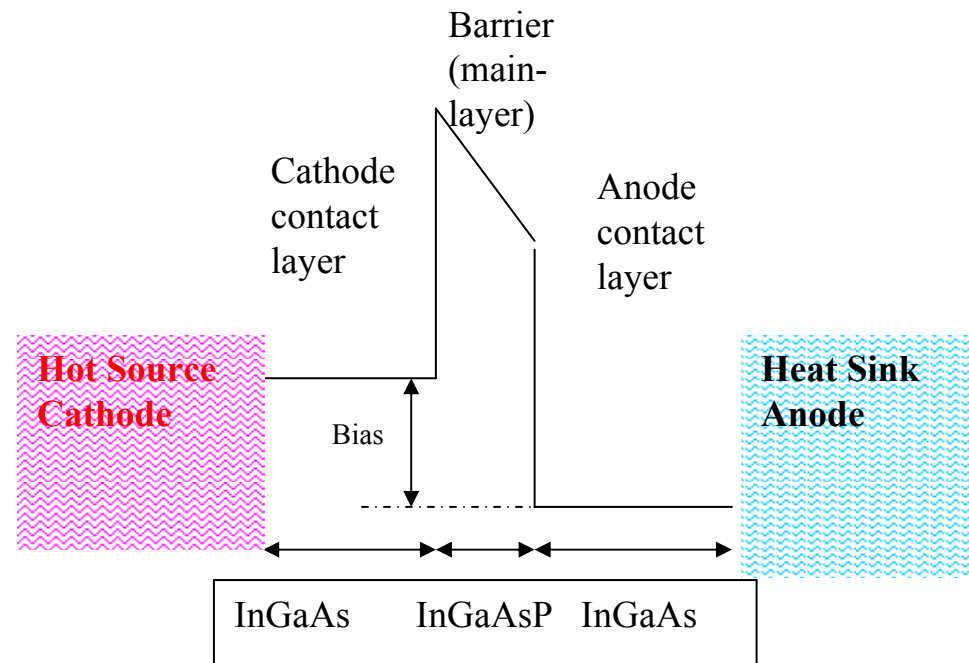
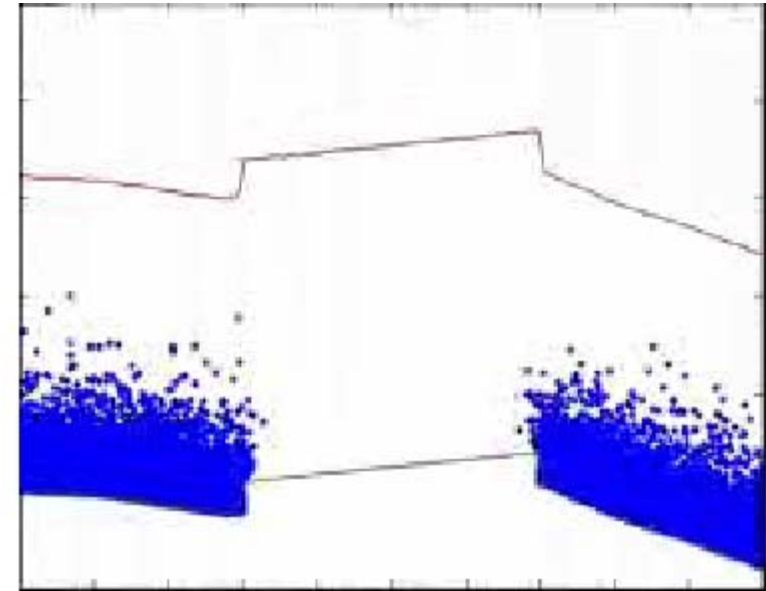
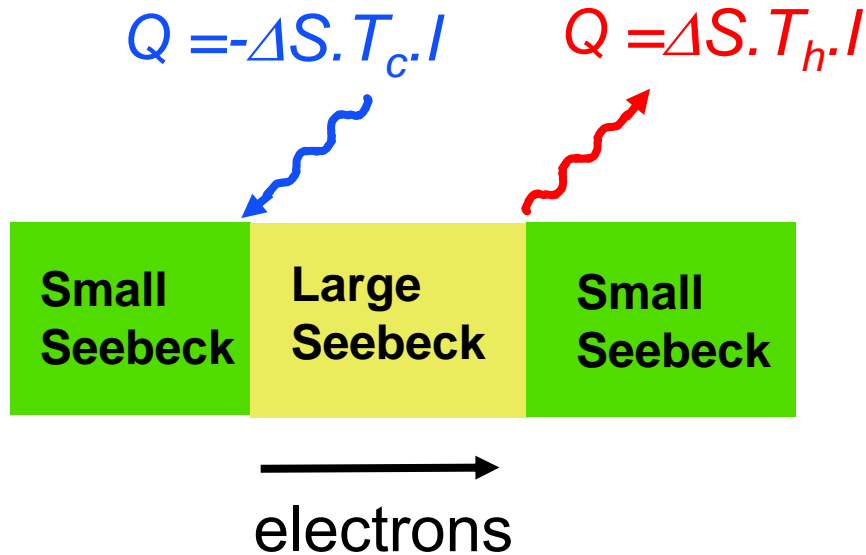
12/15/2008



Mona Zebarjadi, Keivan Esfarjani,
Ali Shakouri (PRB 2006)

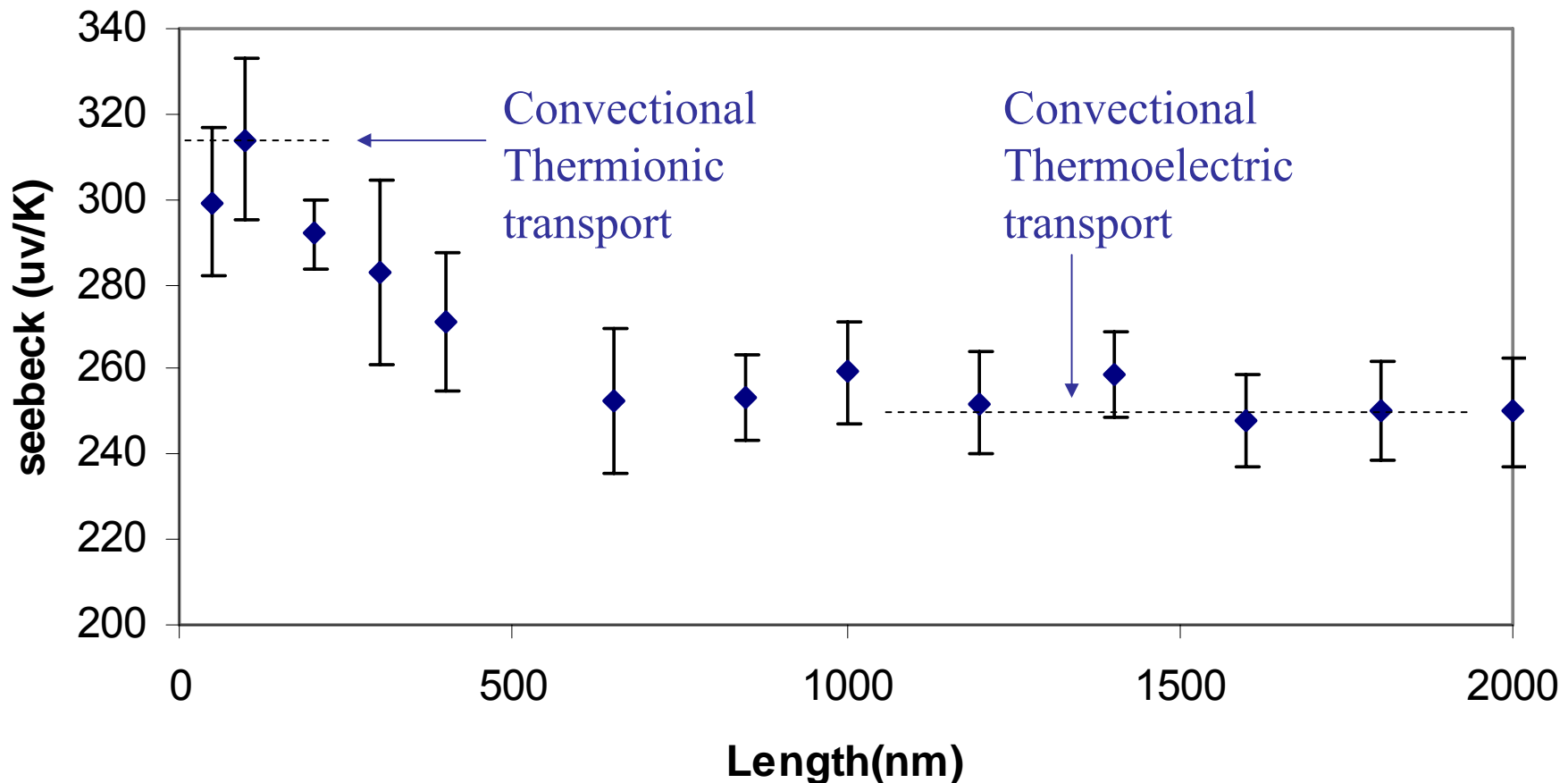
Monte Carlo simulation of TE/TI cooling

AS 4/28/2008



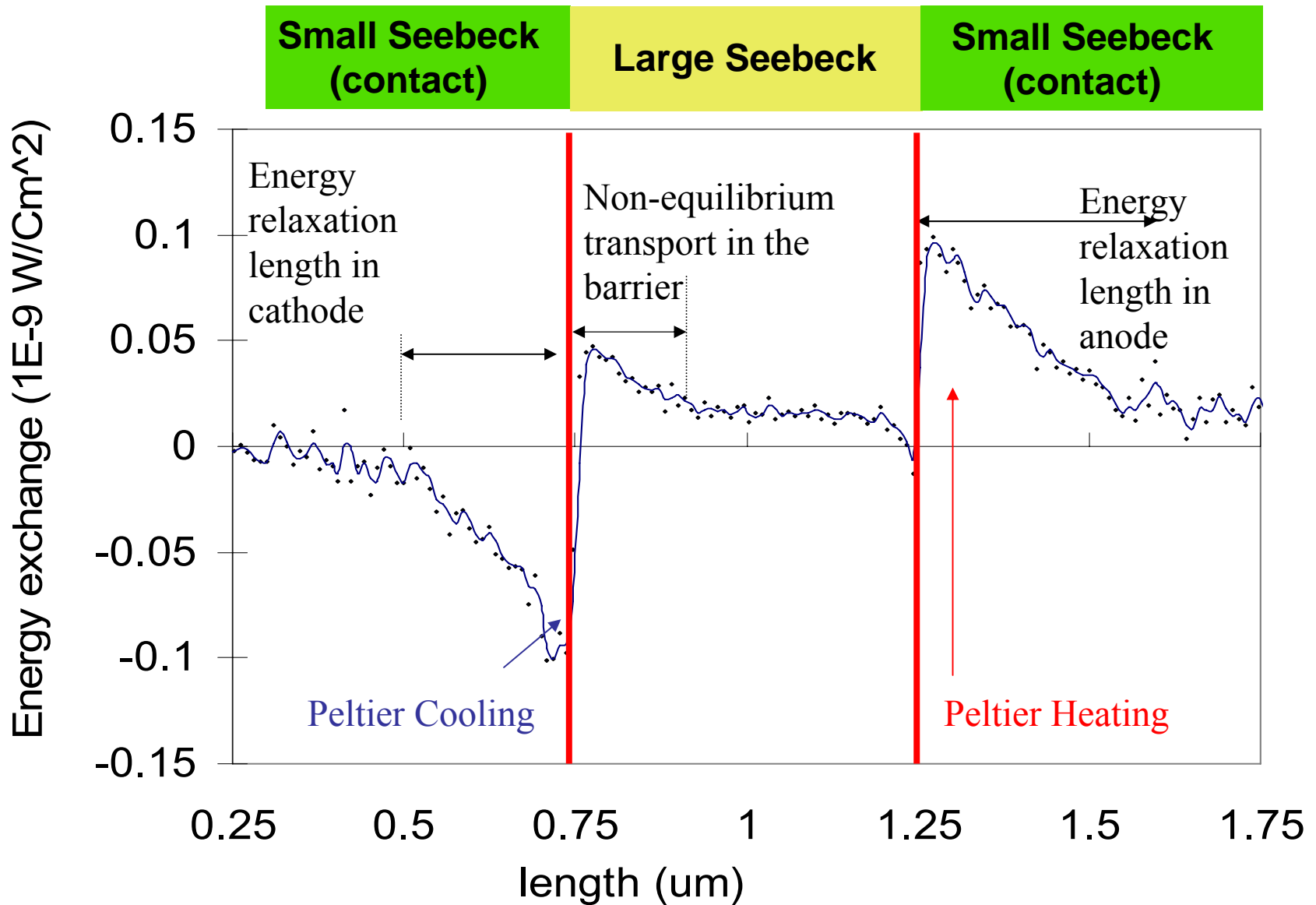
Mona Zebarjadi, Keivan Esfarjani,
Ali Shakouri (PRB 2006)

Effective Seebeck Coefficient vs. Barrier Thickness



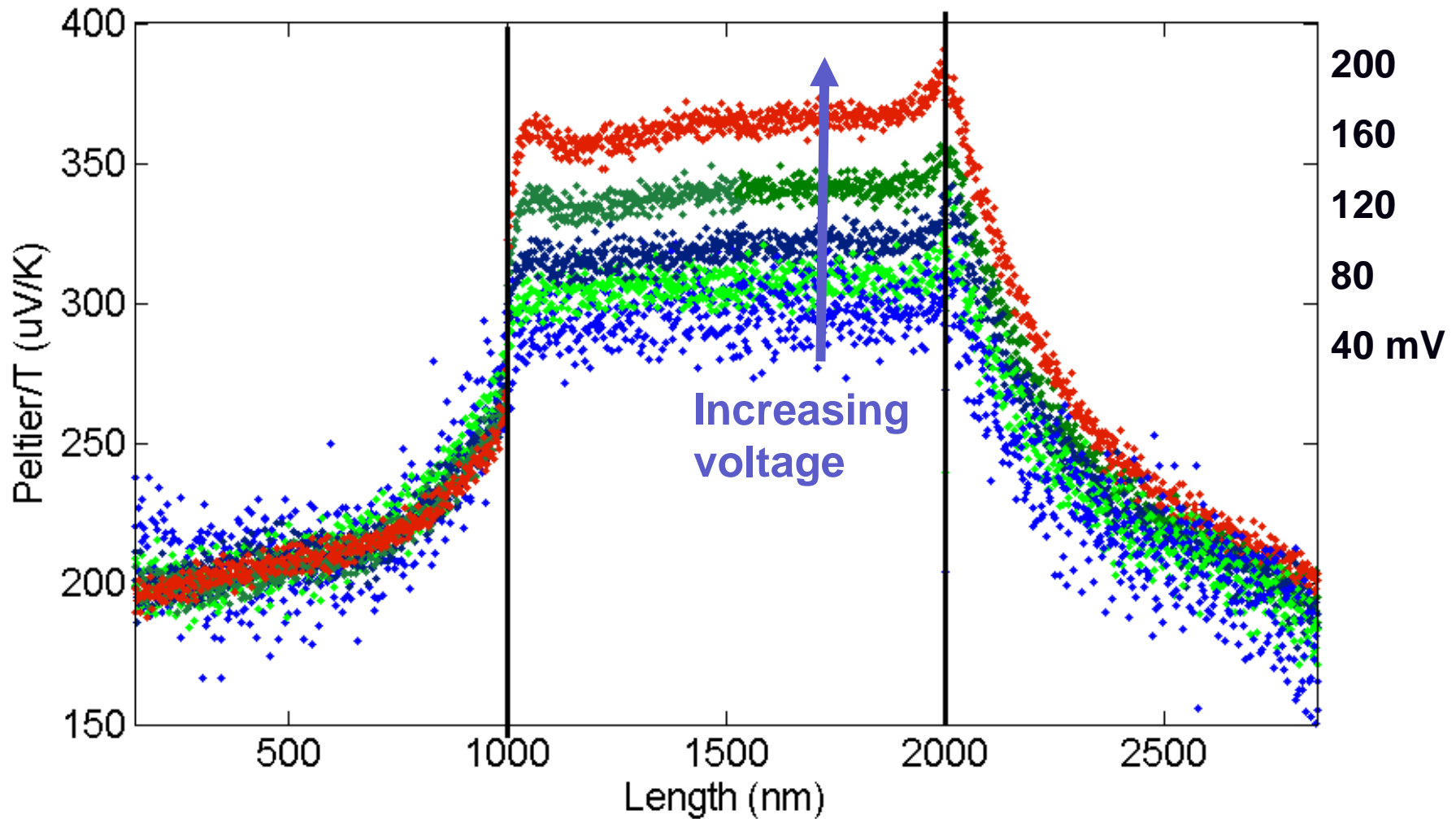
Mona Zebarjadi, Keivan Esfarjani, Ali Shakouri Phys. Rev. B 74, 195331 (2006)

Electron-phonon energy exchange



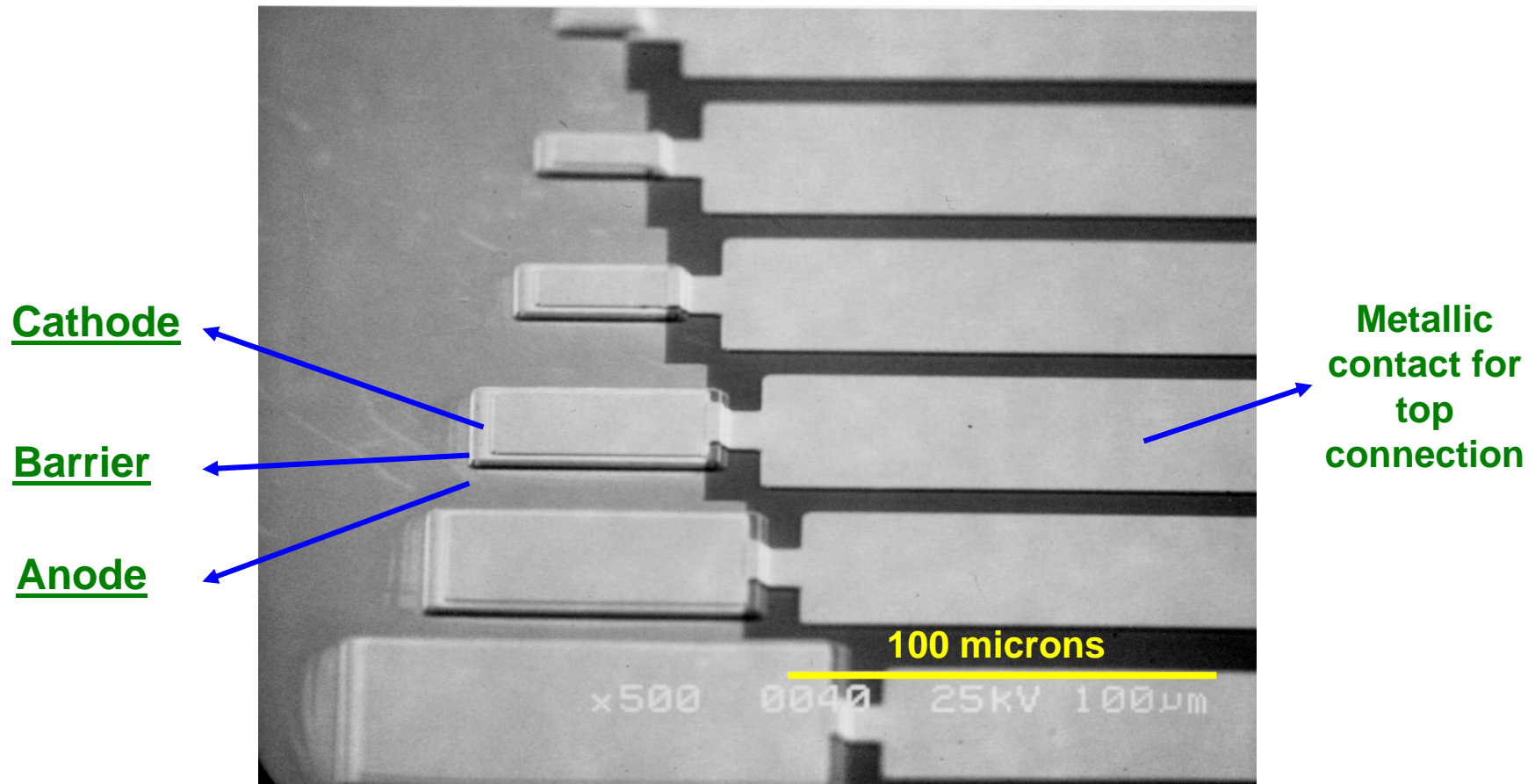
Mona Zebarjadi, K. Esfarjani, A. Shakouri, Phys. Rev. B, 74, 195331 (2006)

Nonlinear Peltier Coefficient



Scanning Electron Micrograph of Thin Film Cooler

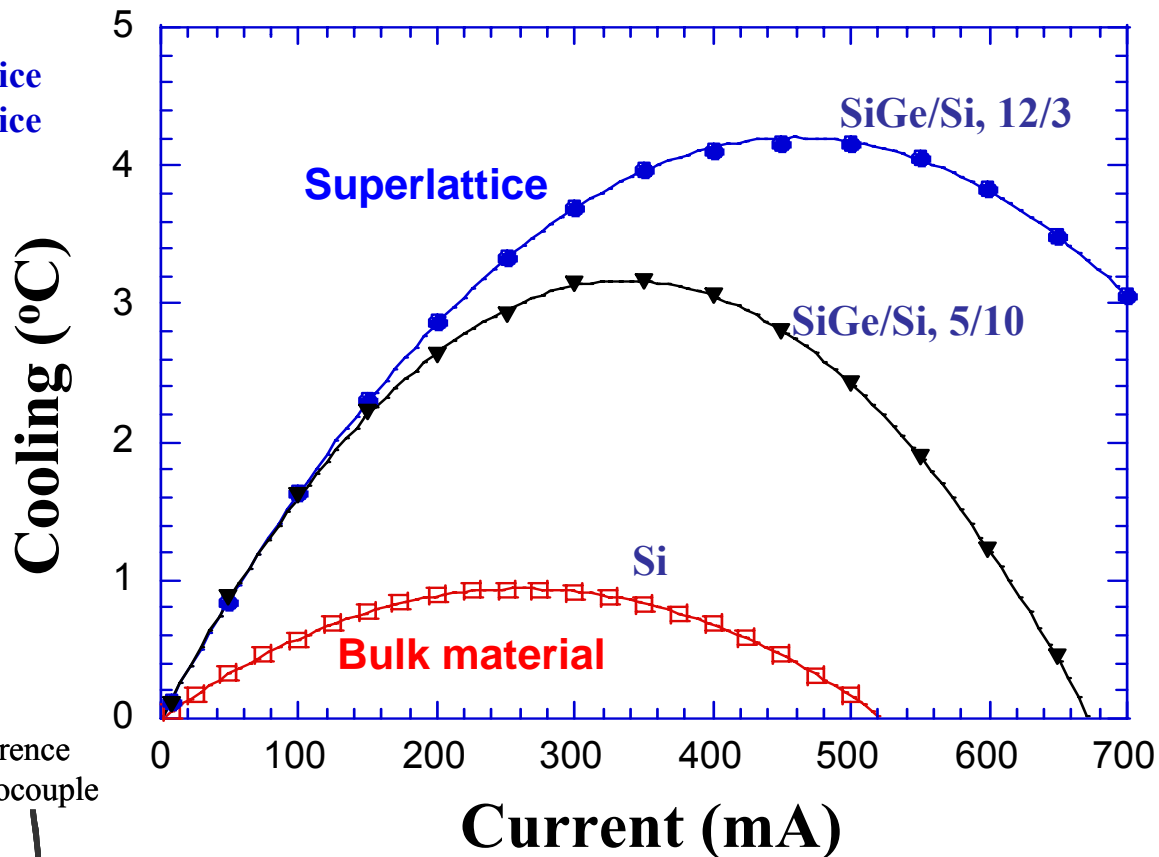
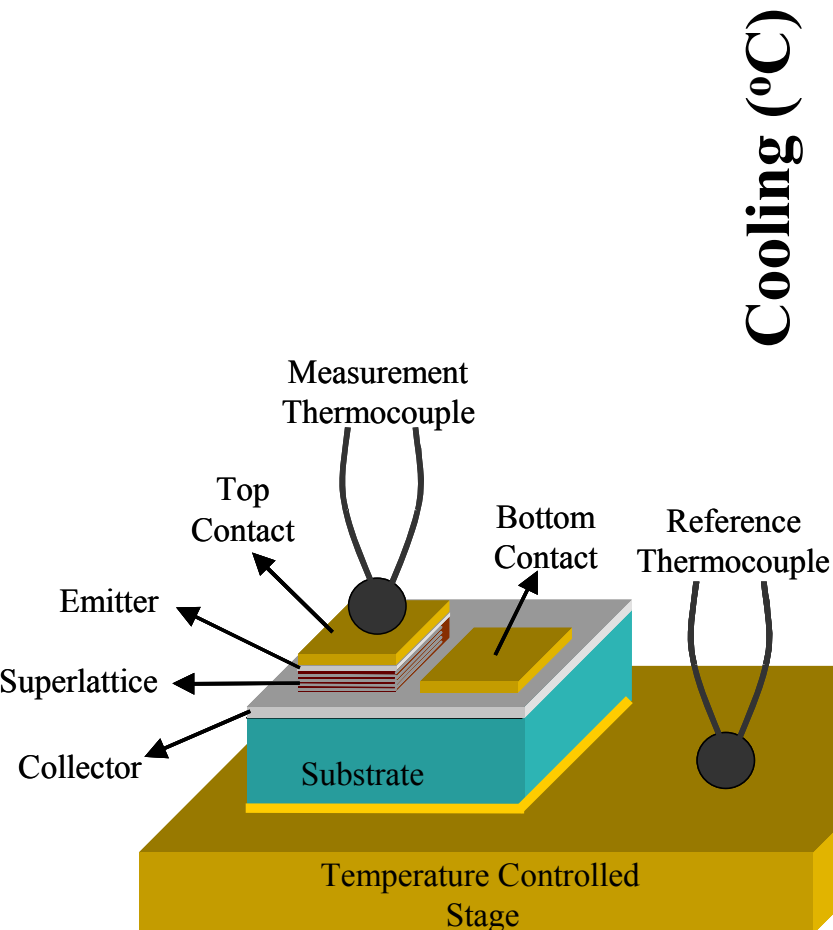
AS 4/28/2008

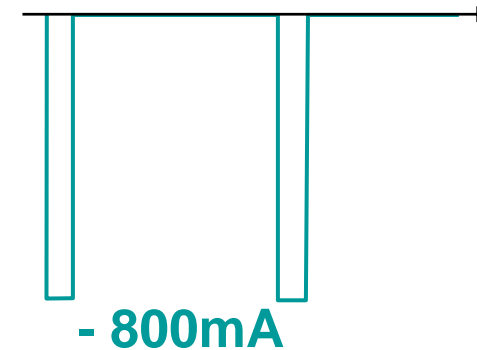
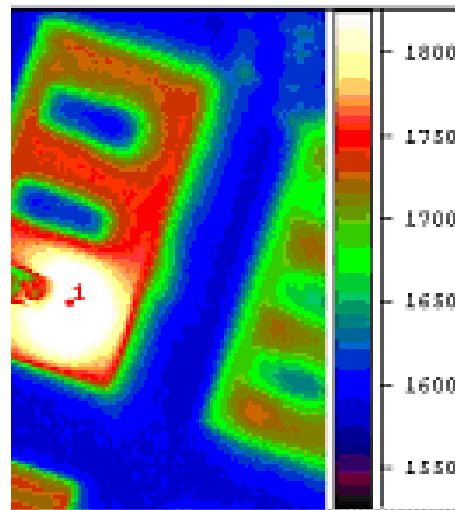
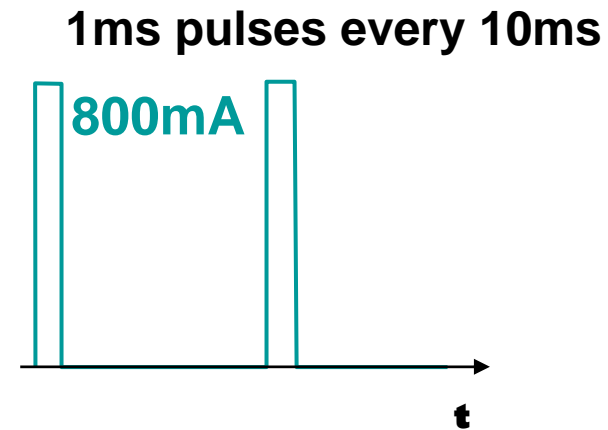
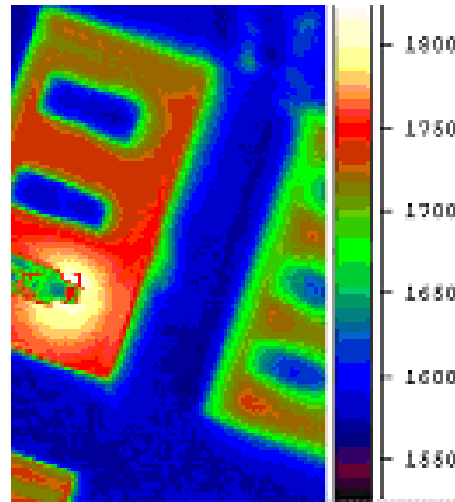


Experimental Cooling vs. Current

AS 4/28/2008

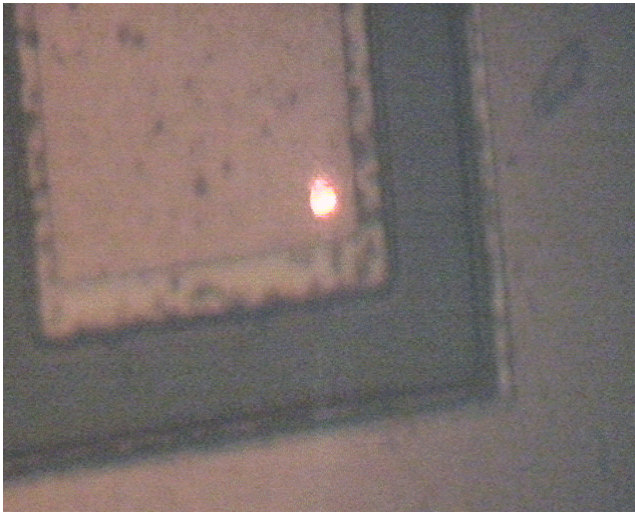
3 μm 200x(12nm Si_{0.75}Ge_{0.25}/3nm Si) superlattice
 3 μm 200x(5nm Si_{0.75}Ge_{0.25}/10nm Si) superlattice
 p+ Si substrate (60x60 μm^2)



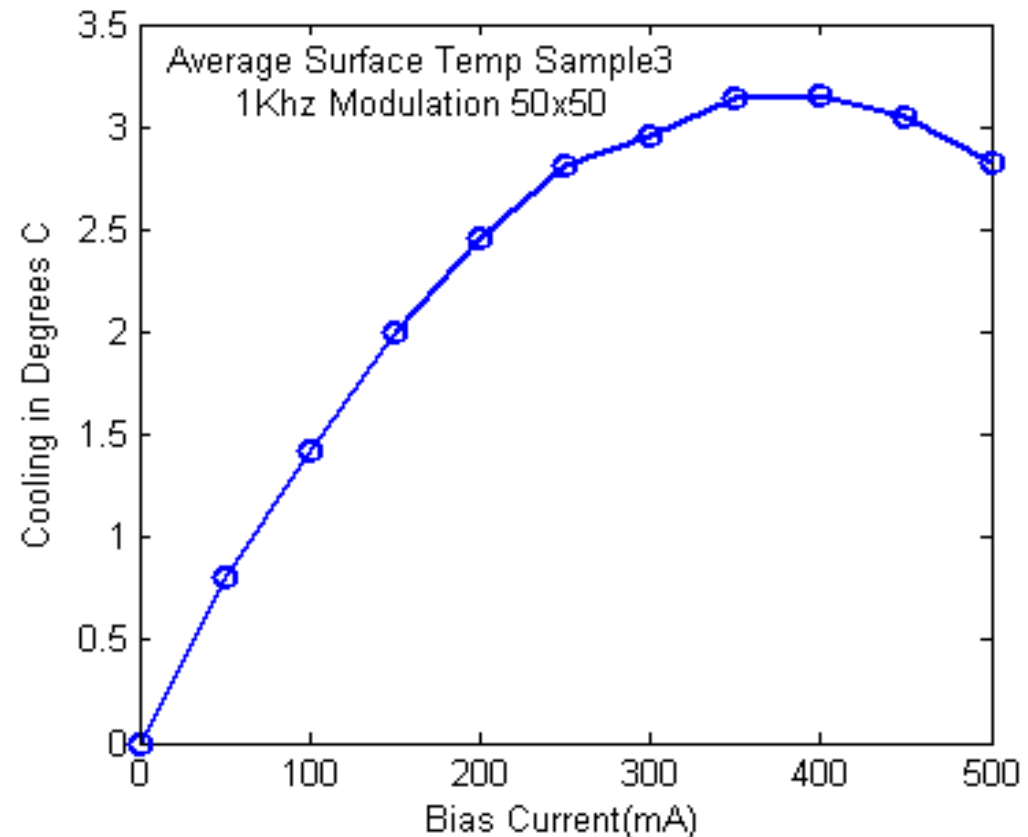


Laser measurement of localized temperature

J. Christofferson et al., SEMITHERM XVII, San Jose, Ca, March 2001.



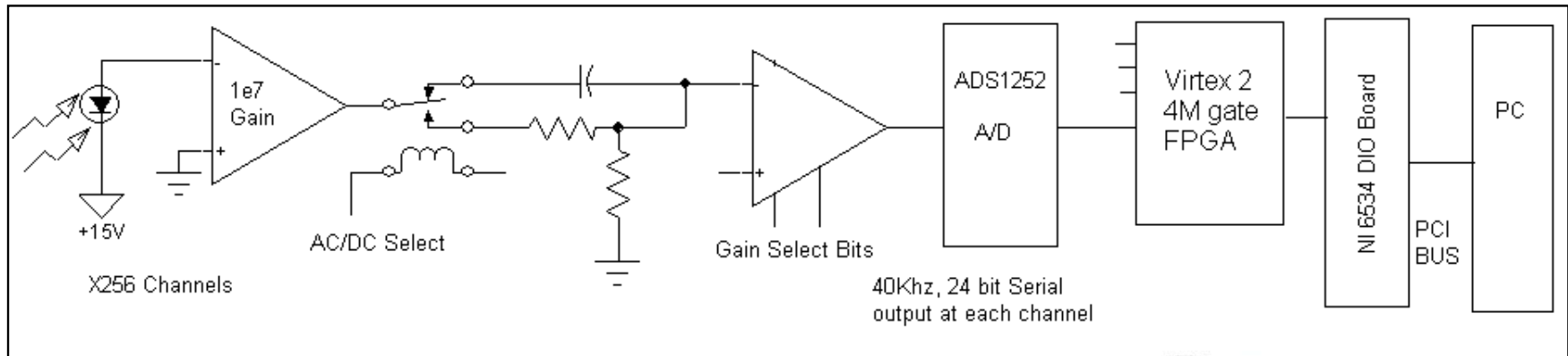
Laser Probe on a micro cooler, lock-in detection at 1KHz



By modulating the device temperature, and by lock-in detection a small change in surface reflectivity due to temperature variation is detected.

Lock-in imaging camera

- AC/DC coupled, dedicated ADC per channel
- FPGA to offload processing

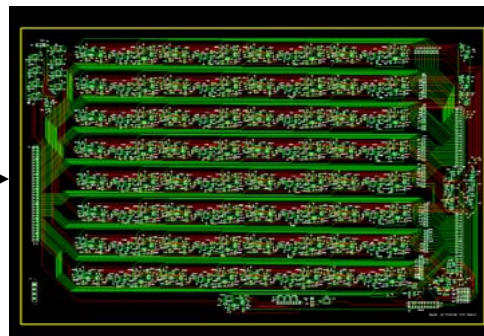


256 Analog

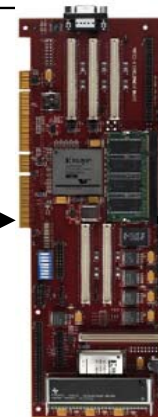
256 serial



Hamamatsu C4675 16x16 pixel photodiode array



Four 64 channel in-house designed signal conditioning, A/D boards



Avnet Development Kit, Virtex2, 128Mb RAM

PCI interface

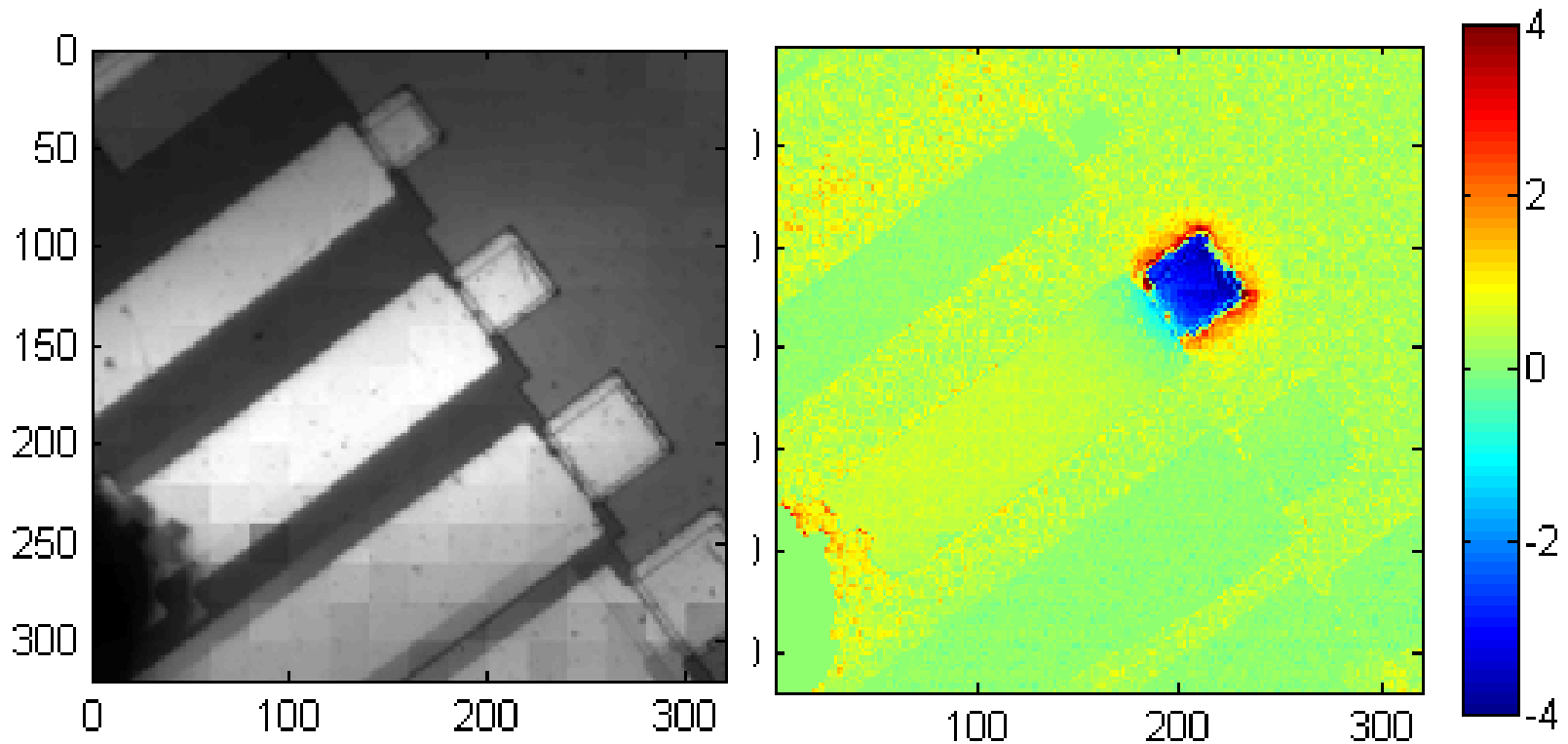


PC running LabVIEW

J. Christofferson,
A. Shakouri
*Review of
Scientific
Instruments*
Feb 2005.

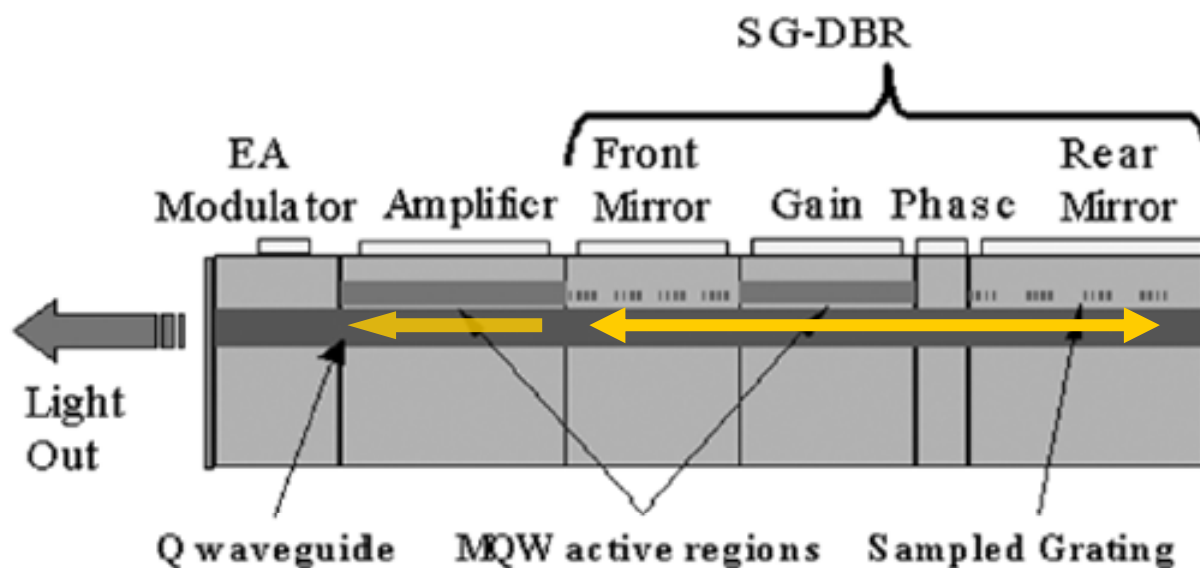
Acquisition time: seconds-minutes

- Temperature resolution: **0.006°C**
- Spatial resolution: **submicron**



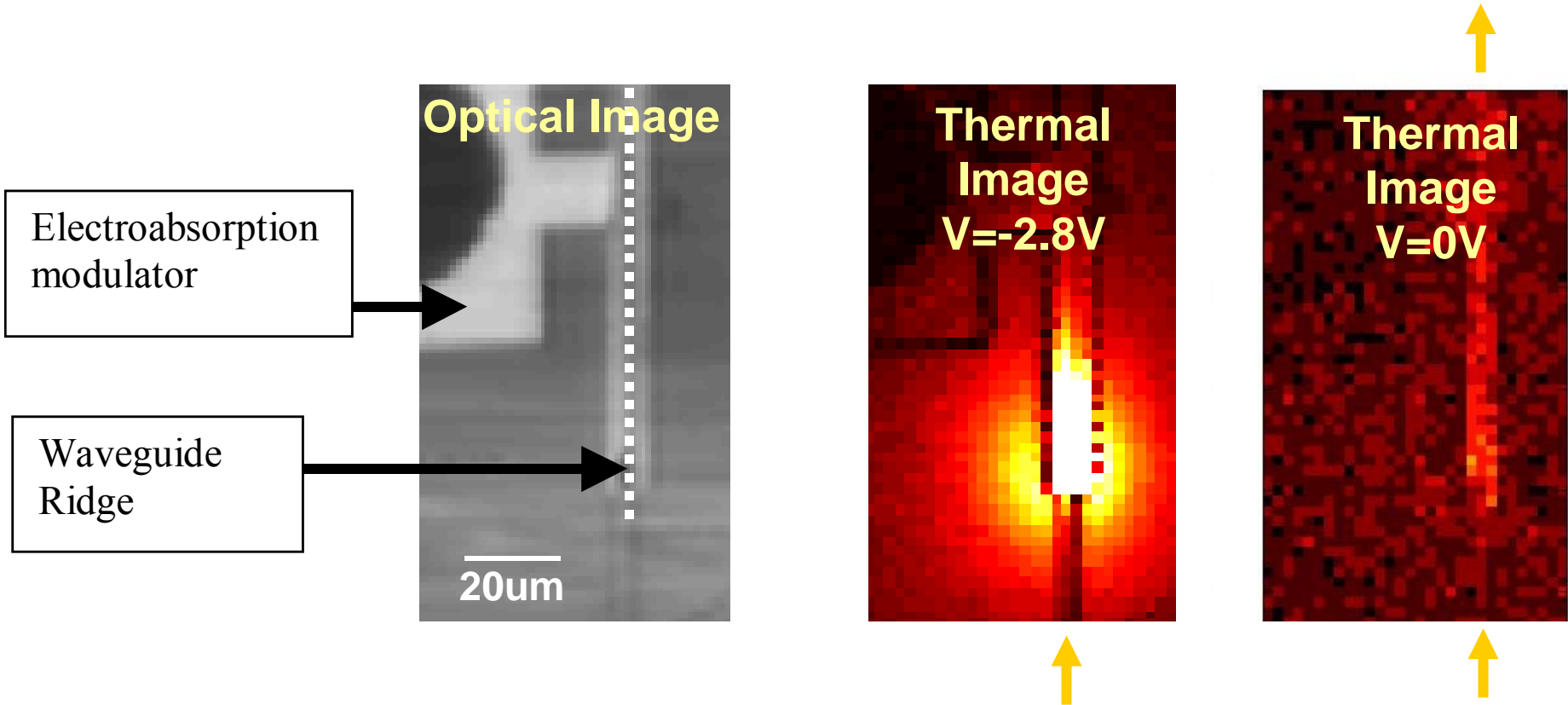
Thermal Issues in Electroabsorption Modulator (EAM)

- EAM can be easily integrated into tunable lasers to offer high bandwidth ($>10\text{Gb/s}$), low chirp, low drive voltage and high extinction ratio



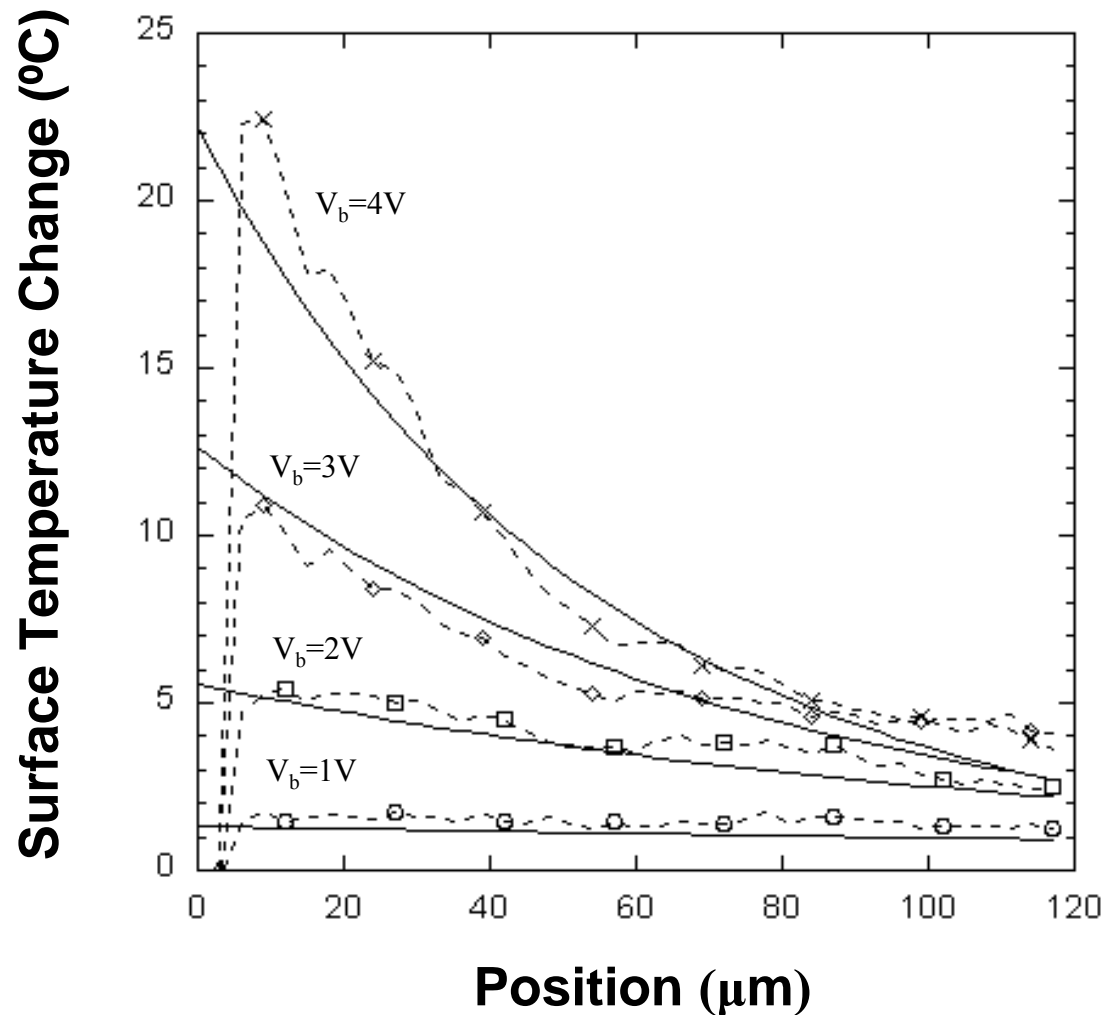
Peter Kozodoy, et al., IEEE Trans. on Components and Packaging Techn., 28 pp. 651, 2005

Thermal Imaging of Integrated Electroabsorption Modulator



Temperature Profile along Modulator at Low Power Operation

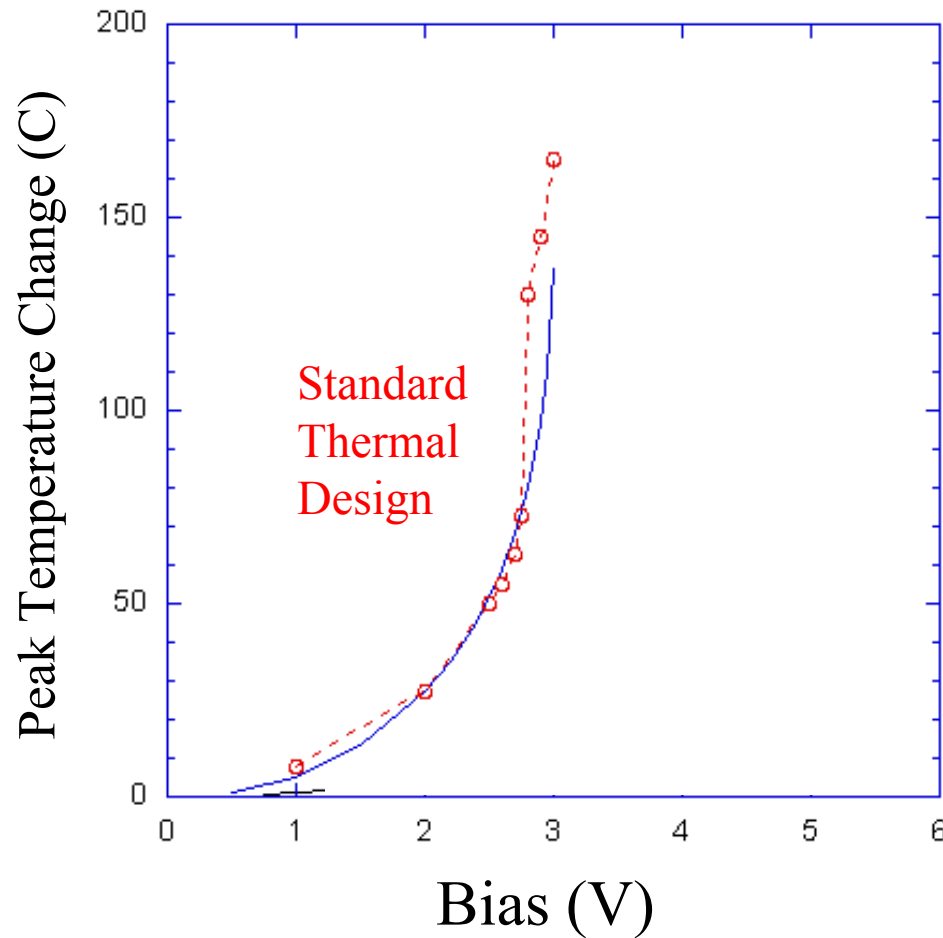
AS 4/28/2008



**Input
power
6mW**

Peak Surface Temperature at High Input Power

AS 4/28/2008



measurement (points)

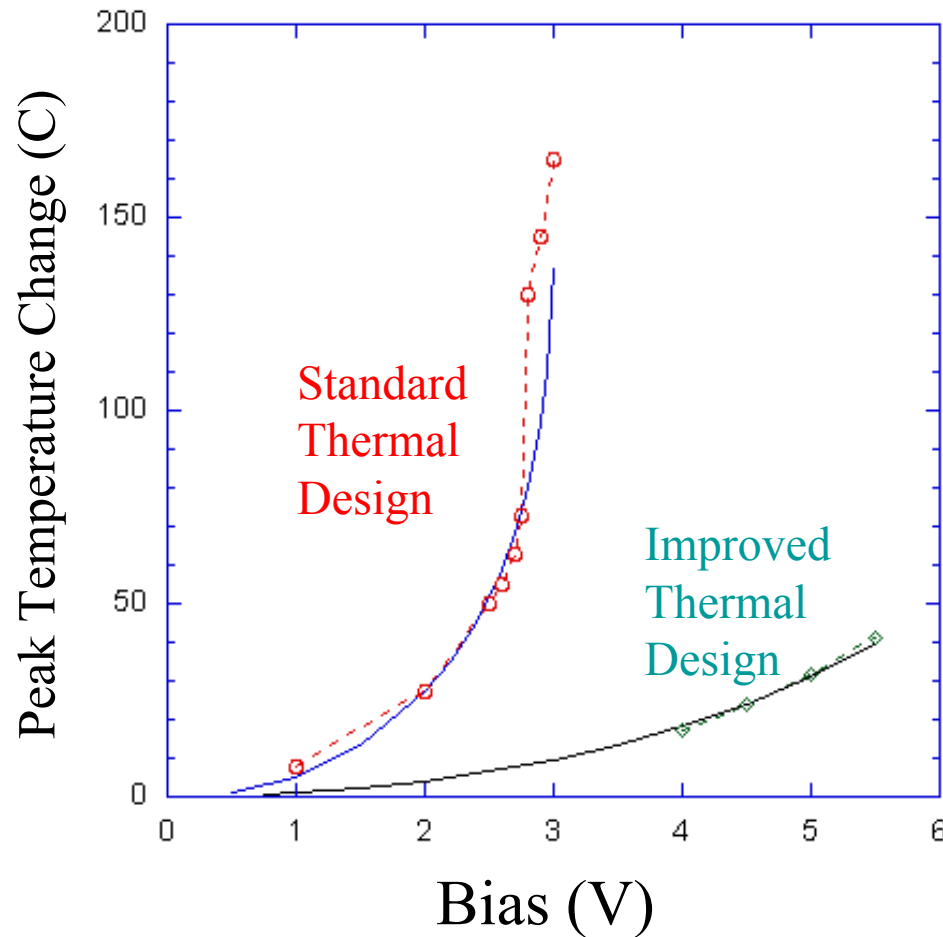
theory (line)

Input power ~ 35 mW
Wavelength ~ 1.55 μm .

There is thermal runaway
with standard device
design

Peak Surface Temperature at High Input Power

AS 4/28/2008



measurement (points)

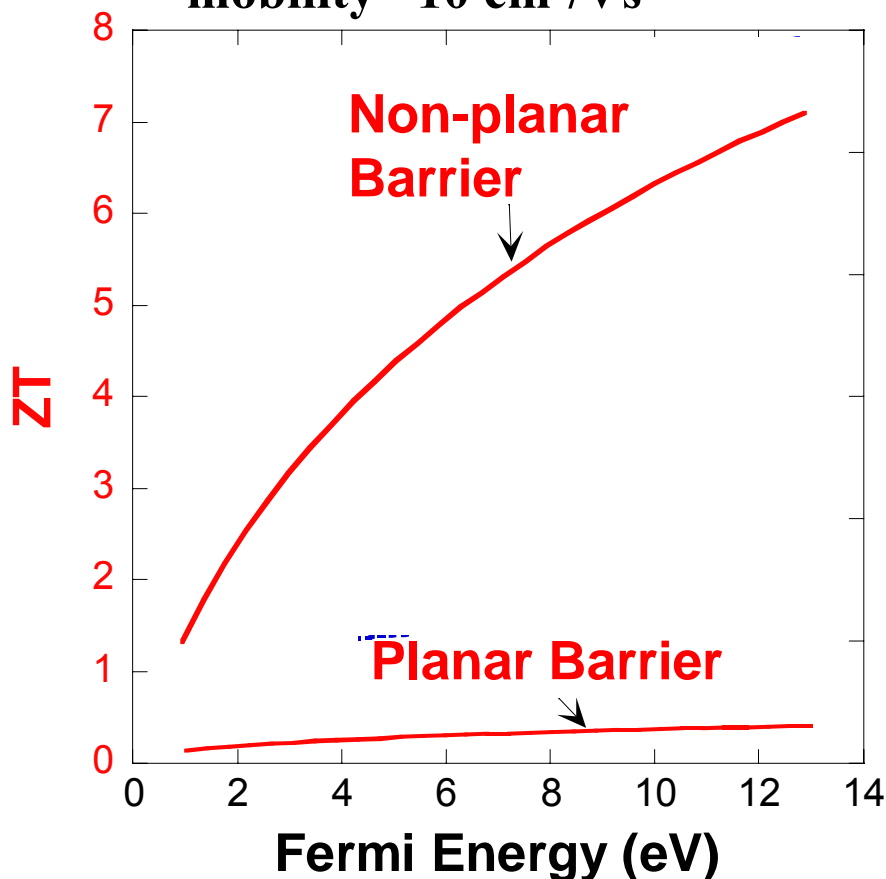
theory (line)

Input power ~ 35 mW
Wavelength ~ 1.55 μm .

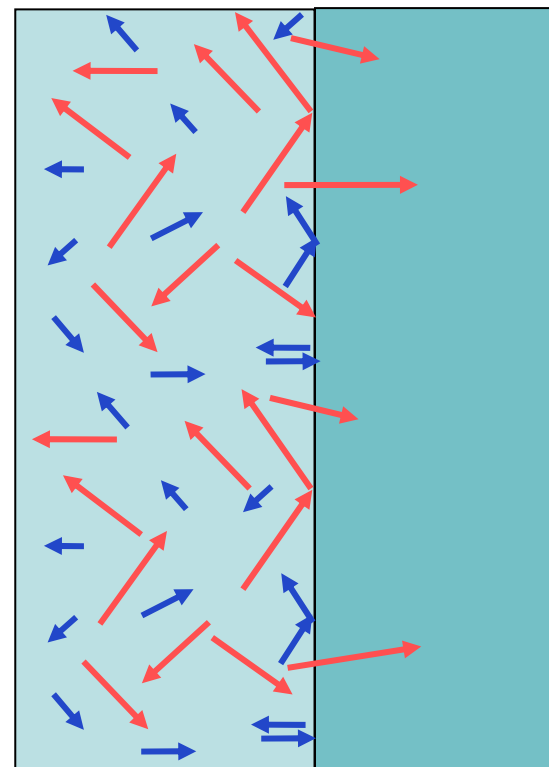
There is thermal runaway with standard device design

ZT for metallic superlattices

Assume: $\beta_{\text{lattice}} = 1 \text{ W/mK}$,
mobility $\sim 10 \text{ cm}^2/\text{Vs}$



Hot and cold electrons in equilibrium Hot electron filter



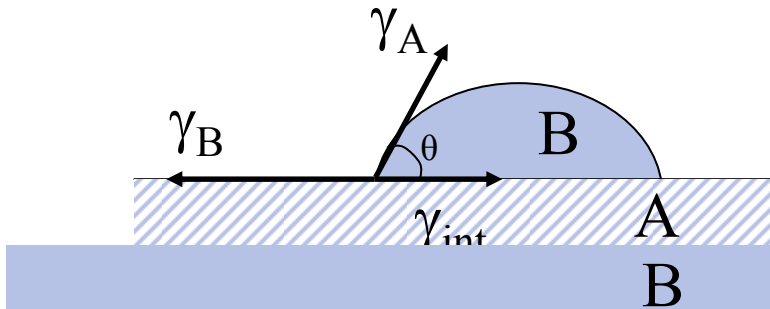
D. Vashaee, A. Shakouri, Physical Review Letters, March 12, 2004

Even with modest low k_{lattice} and mobility of typical metals, $ZT > 5$ is possible with hot electron filters and non-planar barrier.

Can metal/semiconductor multilayers be grown?

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Challenge: No prior examples of metal/semiconductor multilayers or superlattices with nanoscale periods



Late 80's: High speed metal base transistors
→ Not successful

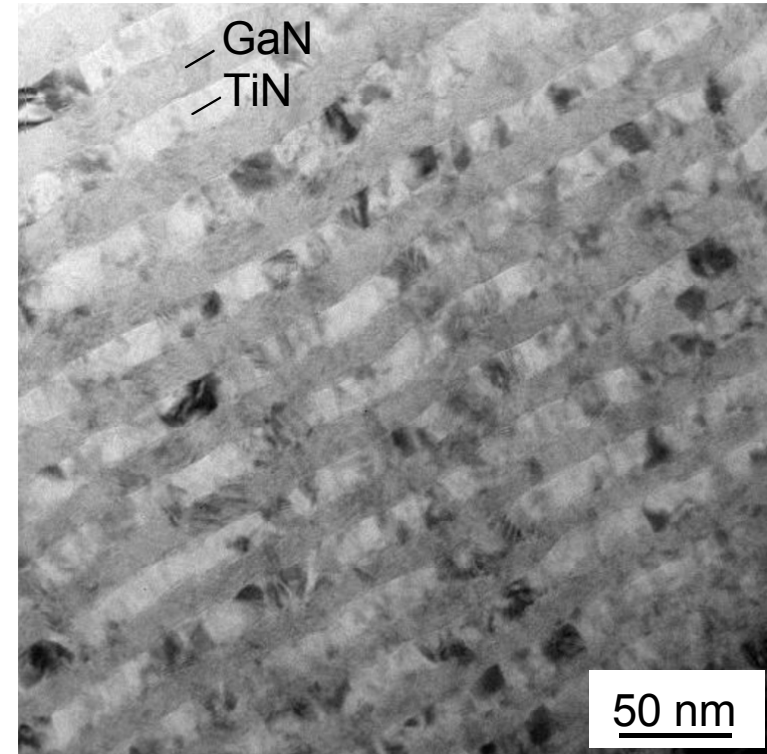
- Minimization of surface energy: If A wets B, B will not wet A.
- Different crystal structures: high defect density; multilayer will not be stable
- Lattice mismatch effect: strain may lead to island growth

Tim Sands (Purdue)

TiN/GaN multilayers for high-T operation

AS 4/28/2008

- **Good metals (e.g., TiN with $\rho = 20 \mu\Omega\text{-cm}$)**
- **Semiconducting (hp-GaN [1.7 eV] and ScN [2.15 eV]) and insulating (hp-AlN) rocksalt nitrides**
- **High melting points (e.g., 3290°C for TiN); negligible sublimation**
- **Excellent corrosion resistance, mechanical hardness and toughness**
- ***But high bulk thermal conductivities (e.g. 130 W/m-K for GaN)***



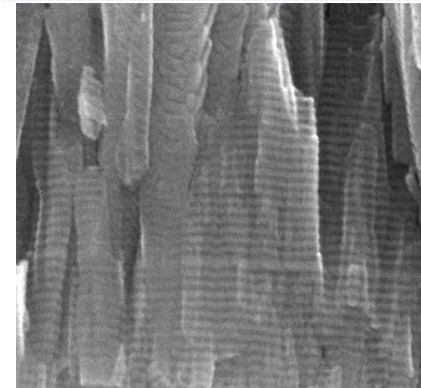
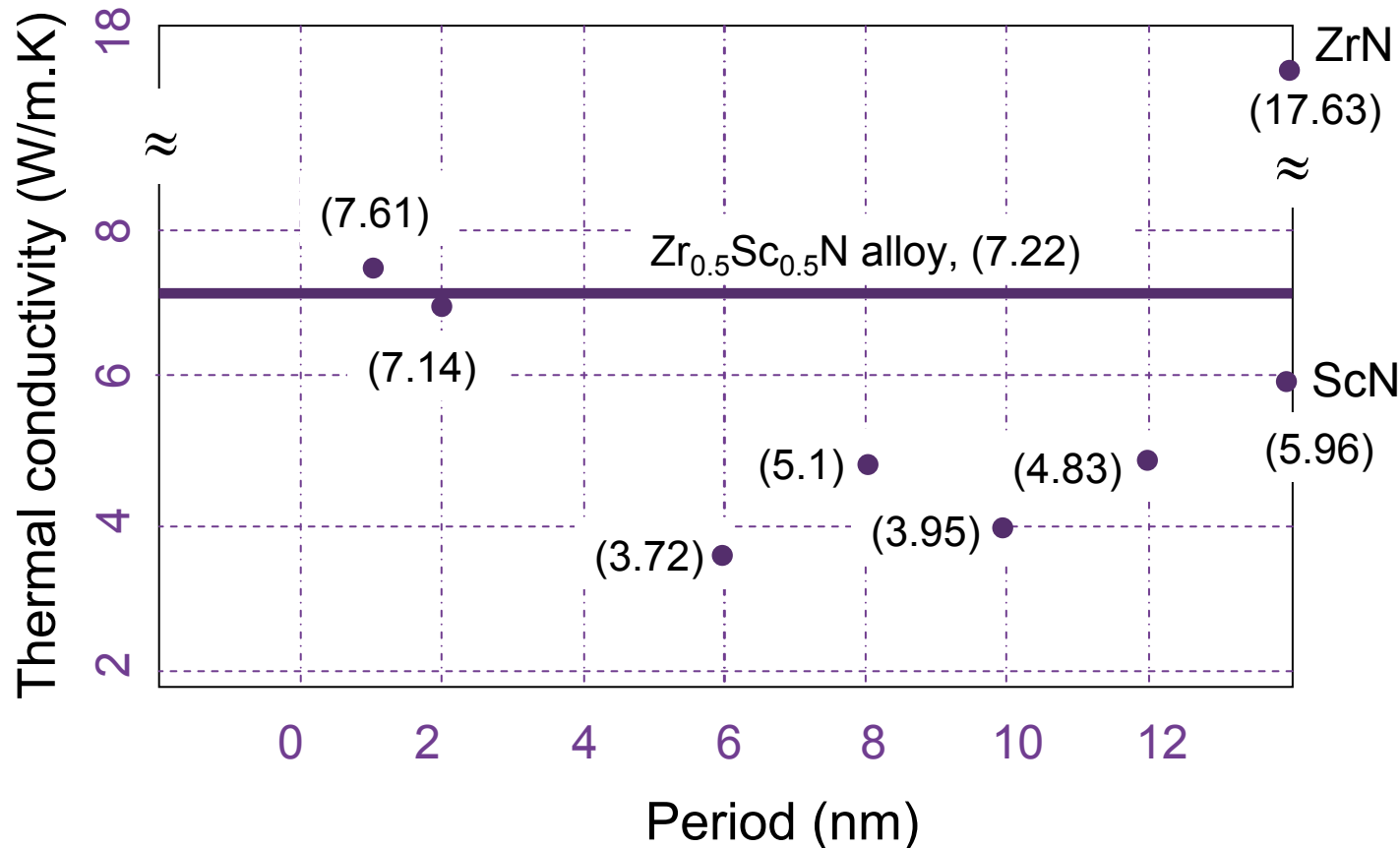
20 nm TiN/variable GaN on (100) MgO

GaN and TiN layers are uniform and pinhole free down to a few nm in thickness

Thermal conductivity of metal/ semiconductor multi layers

Room temperature thermal conductivity as
a function of multilayer period (3ω) -

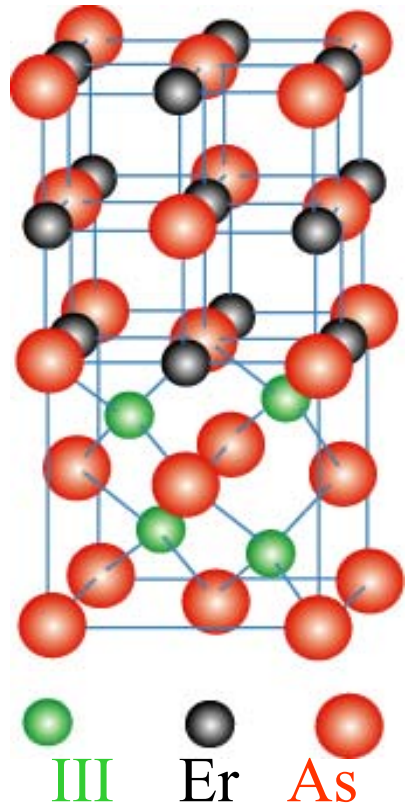
$$k_{\text{multilayer}} < k_{\text{alloy}}$$



1.16 μm thick
ZrN(6nm)/ScN(6nm)
multilayer
grown on MgO
substrate

Rawat, Sands (Purdue), Singer, Majumdar (Berkeley)

Semimetallic Nanoparticles: ErAs/III-V



Semimetal

ErAs (Rock-salt)

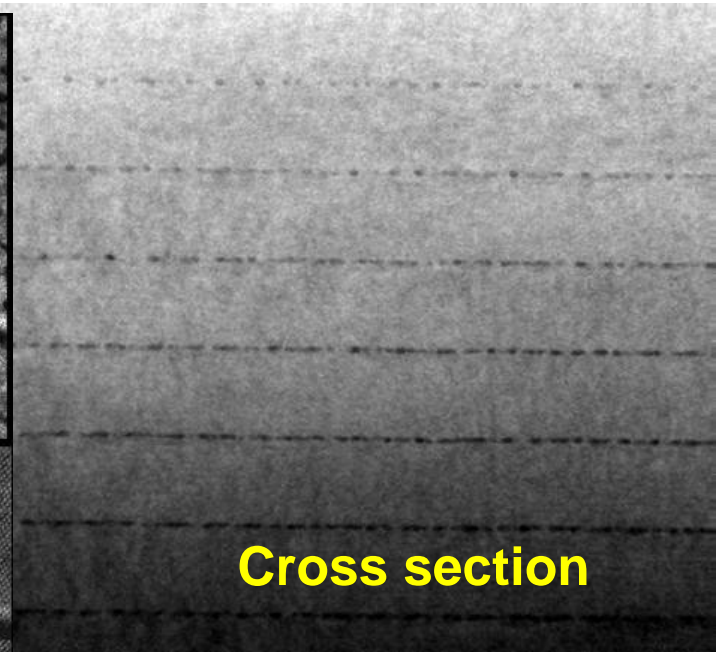
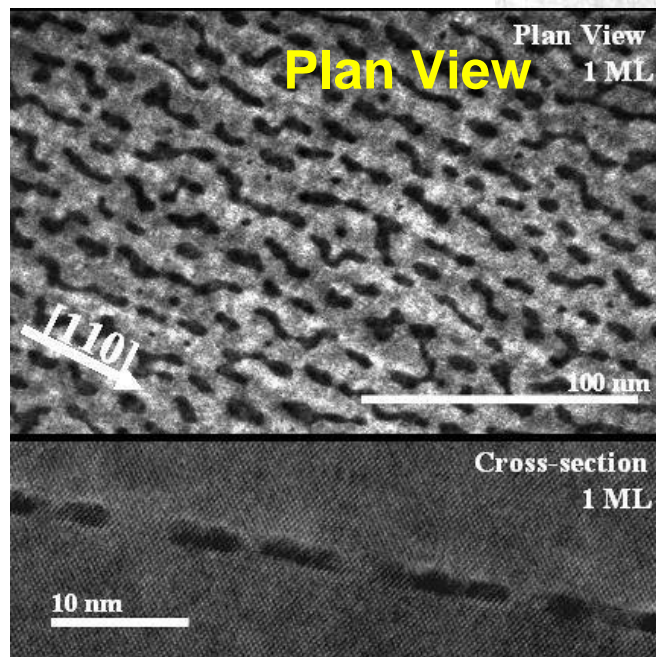
$a=5.74 \text{ \AA}$

Semiconductor

e.g. InGaAs (Zinc blende)

$a=5.85 \text{ \AA}$

- ErAs is a rocksalt semimetal with a fairly small lattice mismatch to several III-V semiconductors.
- It can be grown epitaxially on the semiconductor, and the arsenic has a continuous fcc sublattice.



Co-deposited ErAs Particles in InGaAs

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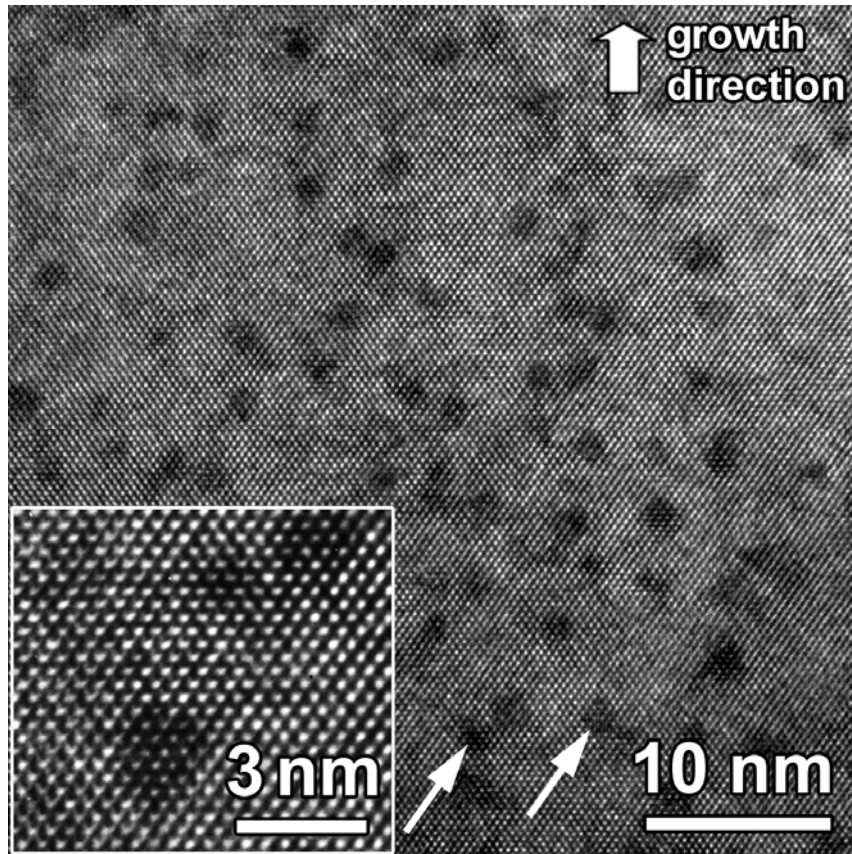
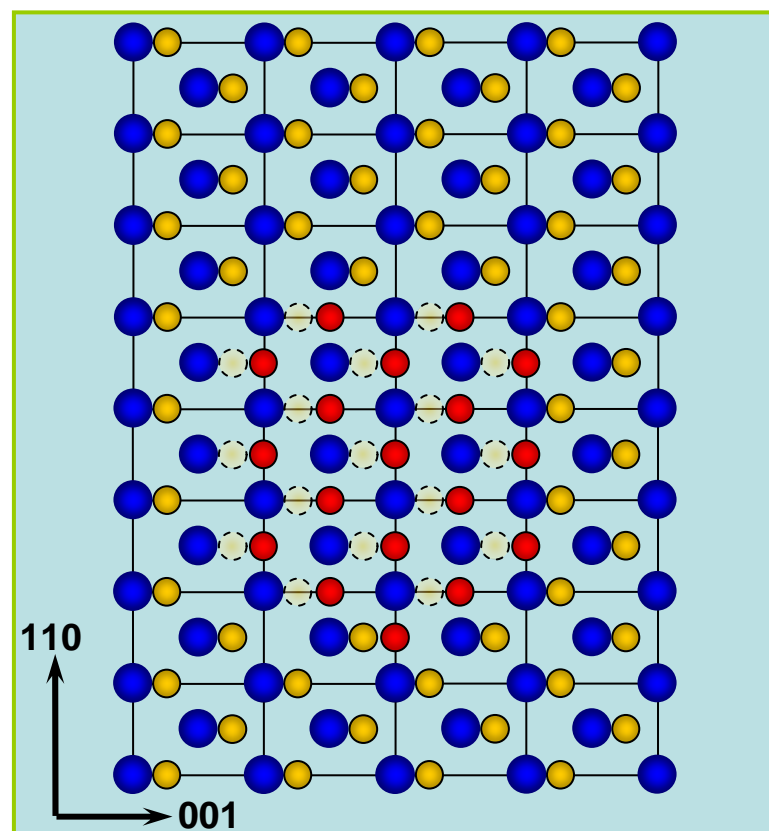
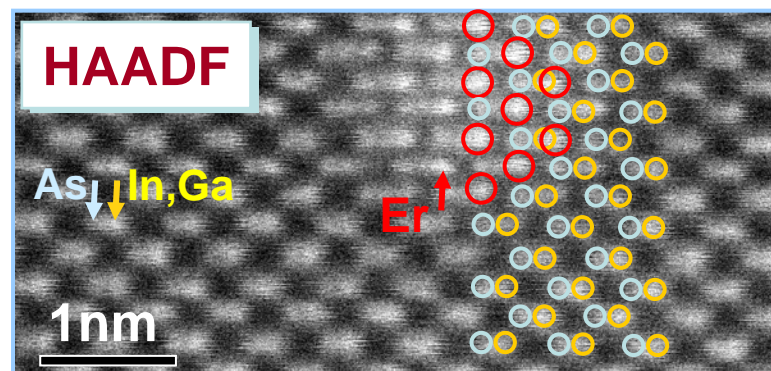
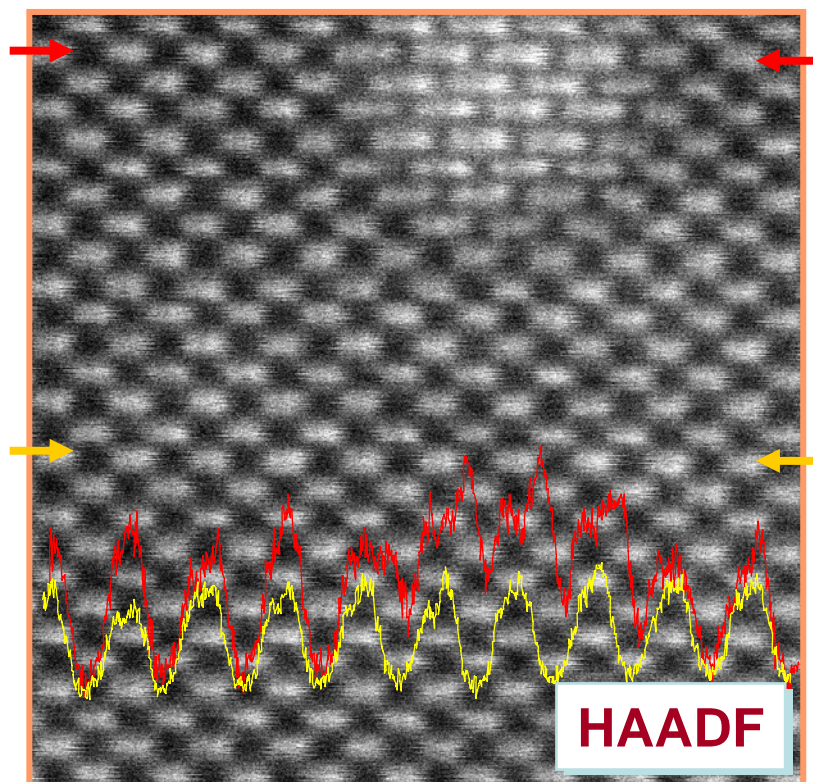


Image from D. Klenov
J.M. Zide, *et al.* Appl. Phys. Lett. **87**, 112103 (2005)

- Erbium is co-deposited at a growth rate which is a fixed fraction of the InGaAs growth rate.
- Solubility limit is exceeded → islands are formed.
- Size is similar to that of very small (0.05ML) depositions.

HAADF/STEM of ErAs Nanoparticles

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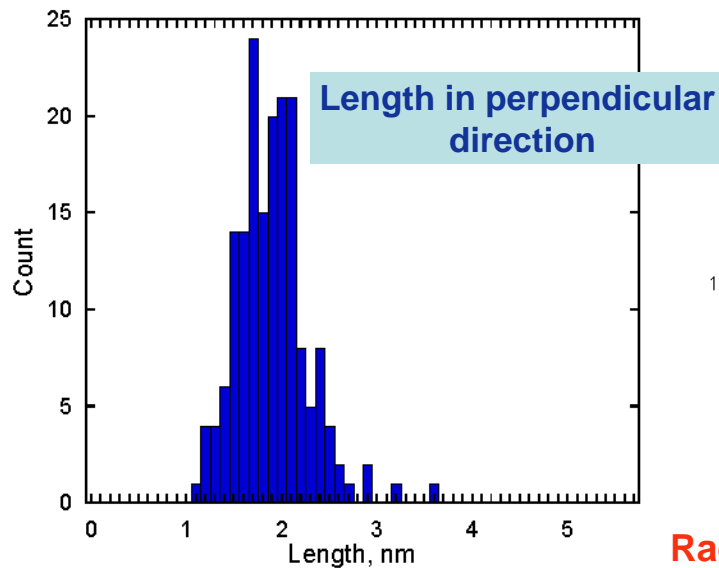
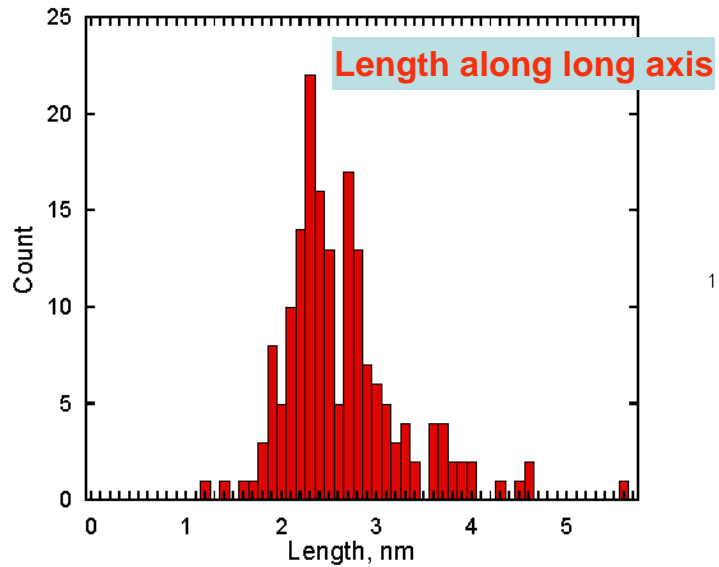


STEM images show that the ErAs particles have the rock salt structure. The As sublattice is continuous across the interface.

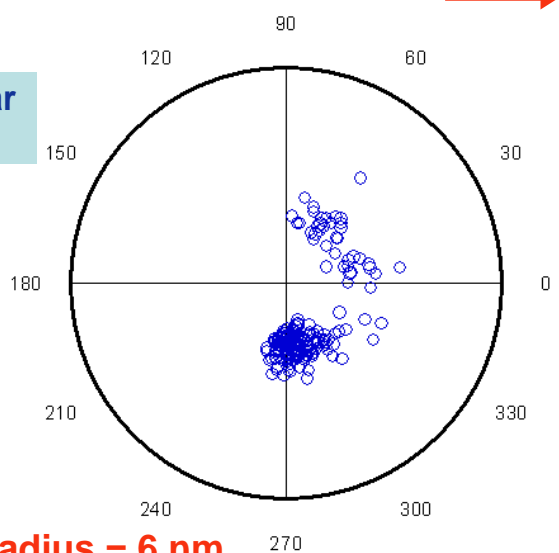
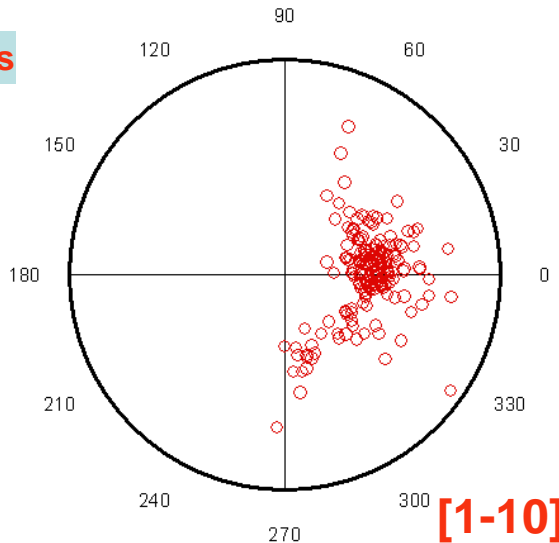
D. O. Klenov, D. C. Driscoll, A. C. Gossard, S. Stemmer, *Appl. Phys. Lett.* 86, 111912 (2005)

Particle sizes and shapes for 3% ErAs

Size



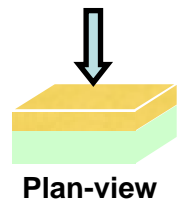
Orientation

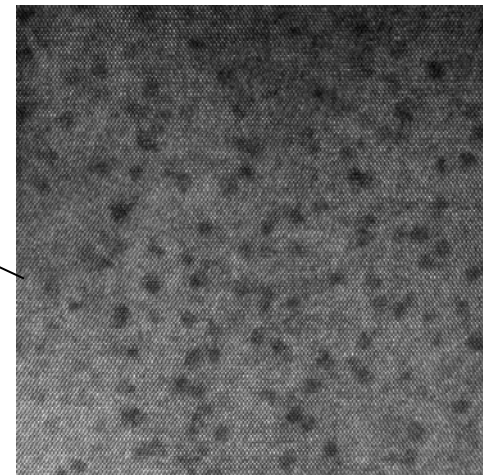
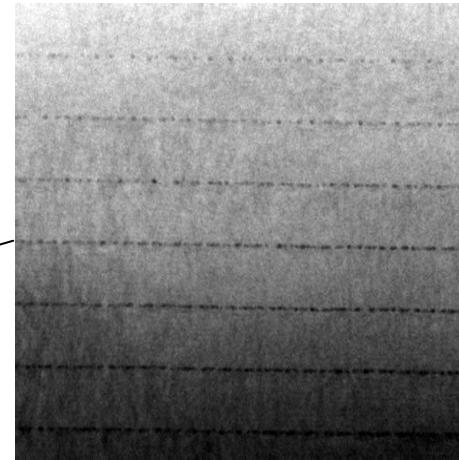
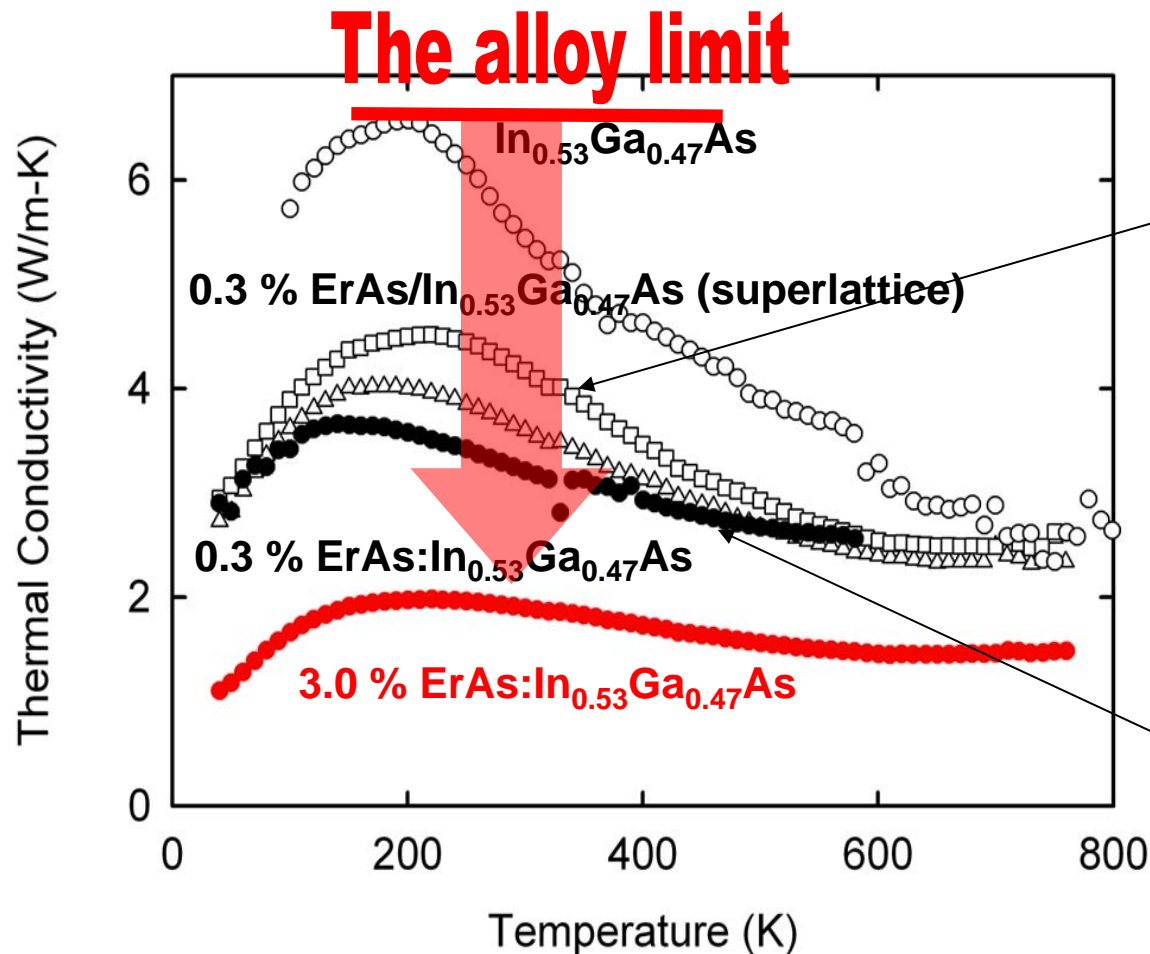


Radius = 6 nm

• Particles are slightly elongated (~ 28%) along the fast [1-10] diffusion direction

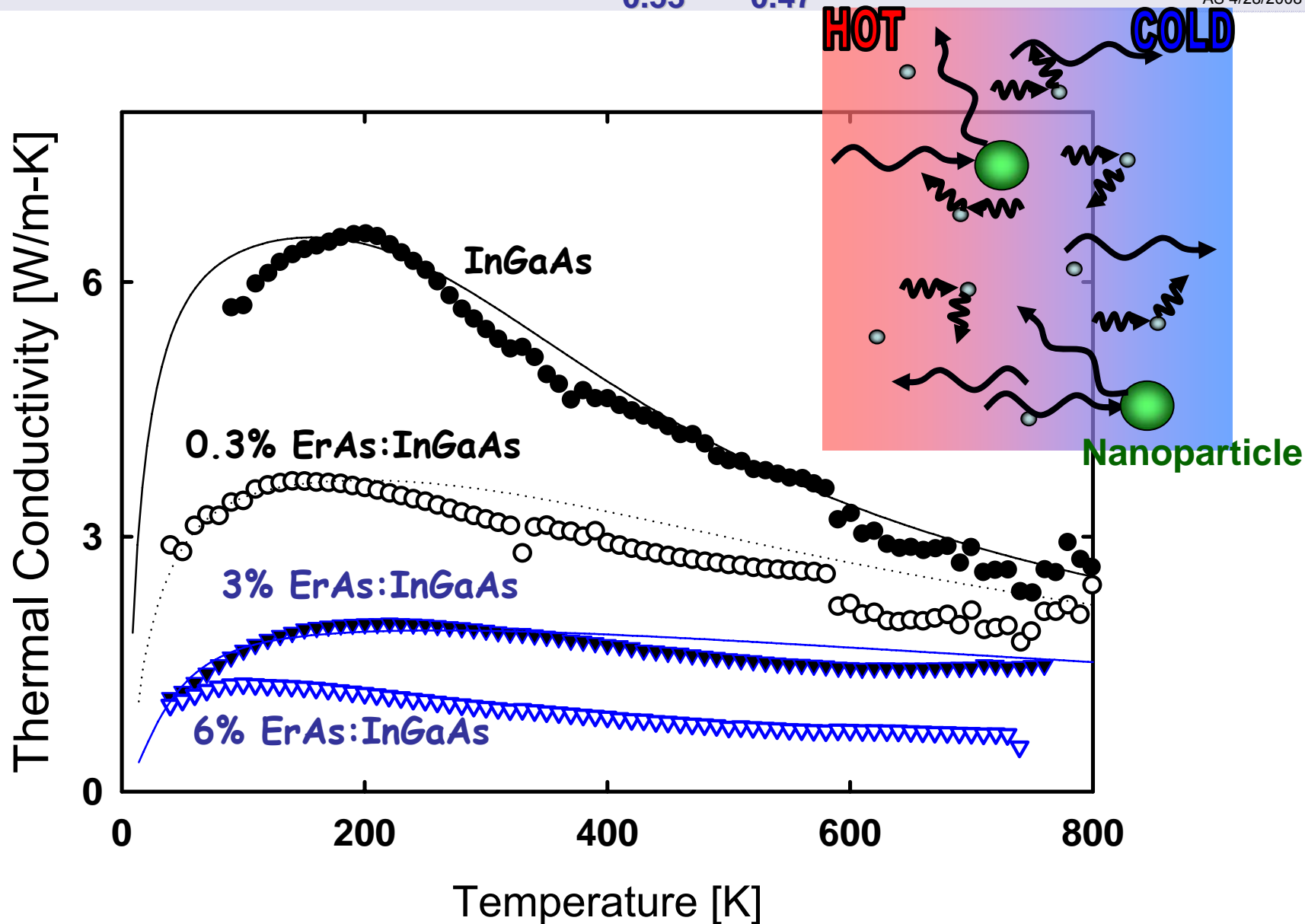
Similar results as for superlattices.



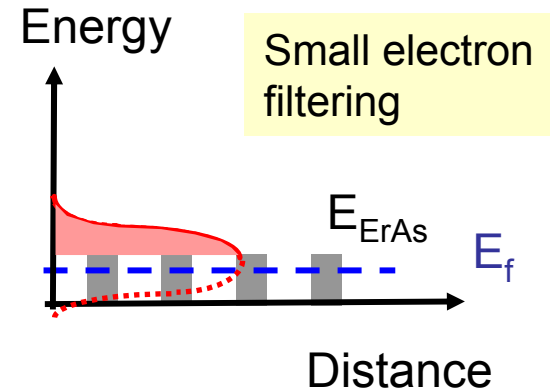
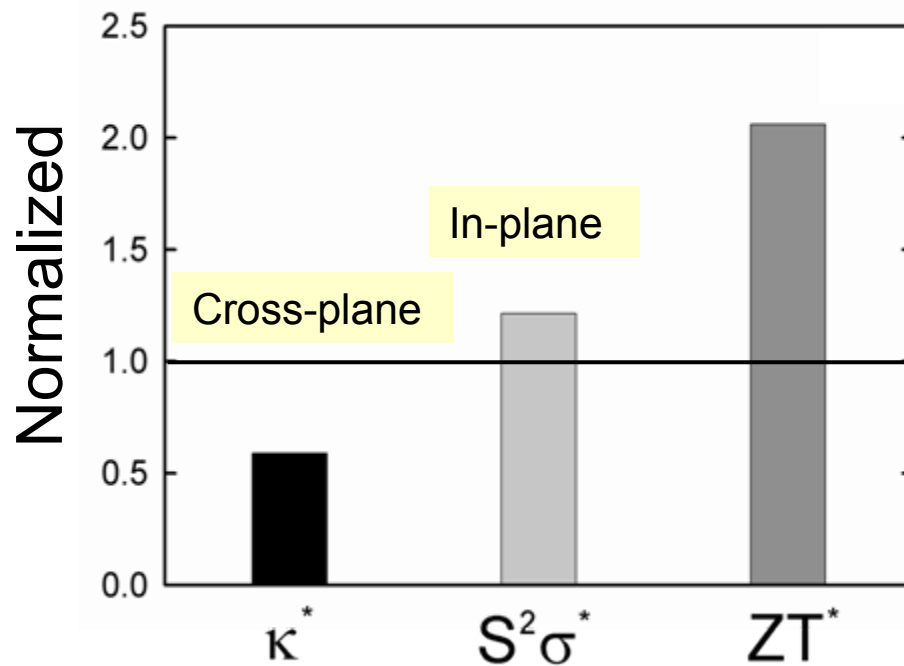


Superlattice to “Random” Nanoparticle Distribution

- Improved Performance (k lower)
- Faster Depositions (MBE grown $60\mu\text{m}$ films)



Thermal conductivity, power factor, ZT of randomly distributed ErAs (0.3%) nanoparticles in InGaAs normalized to those of InGaAs

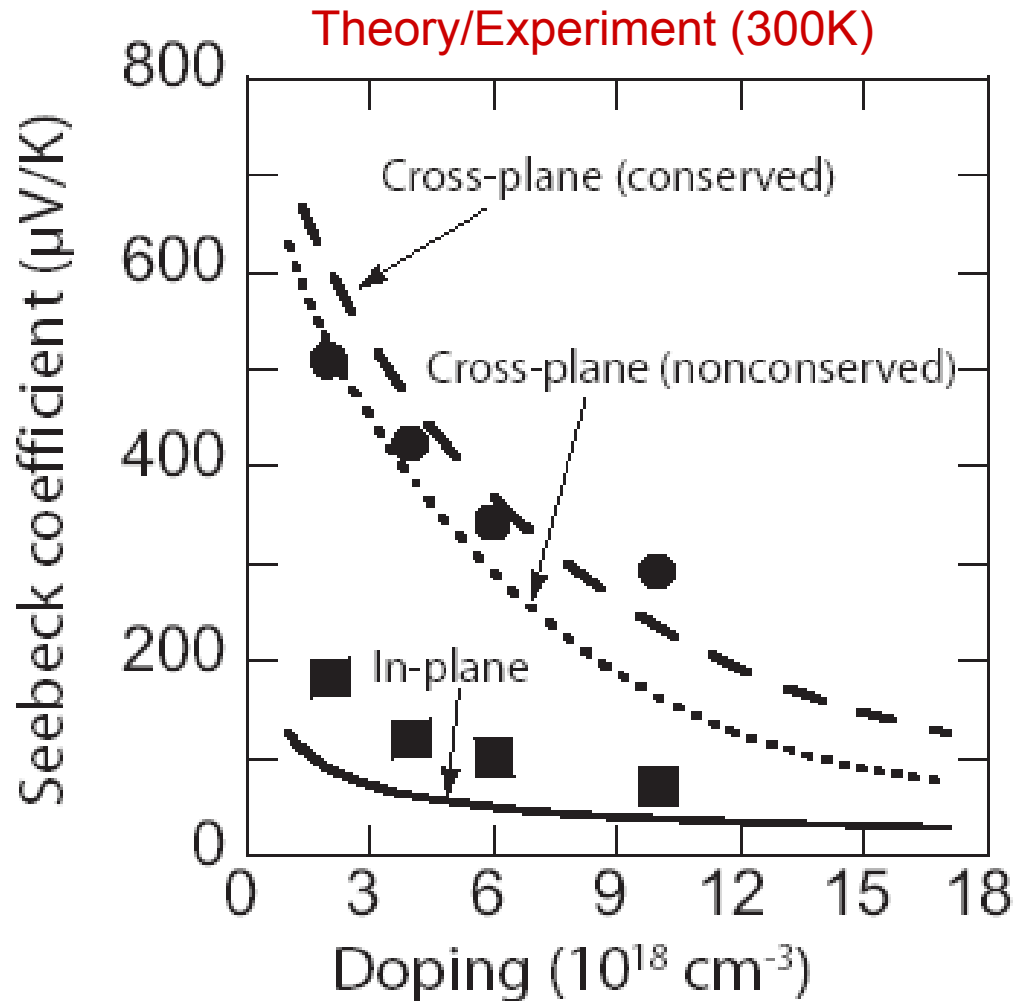


- Energy Filtering in ErAs:InGaAs is small
=> Small enhancement in Seebeck coefficient

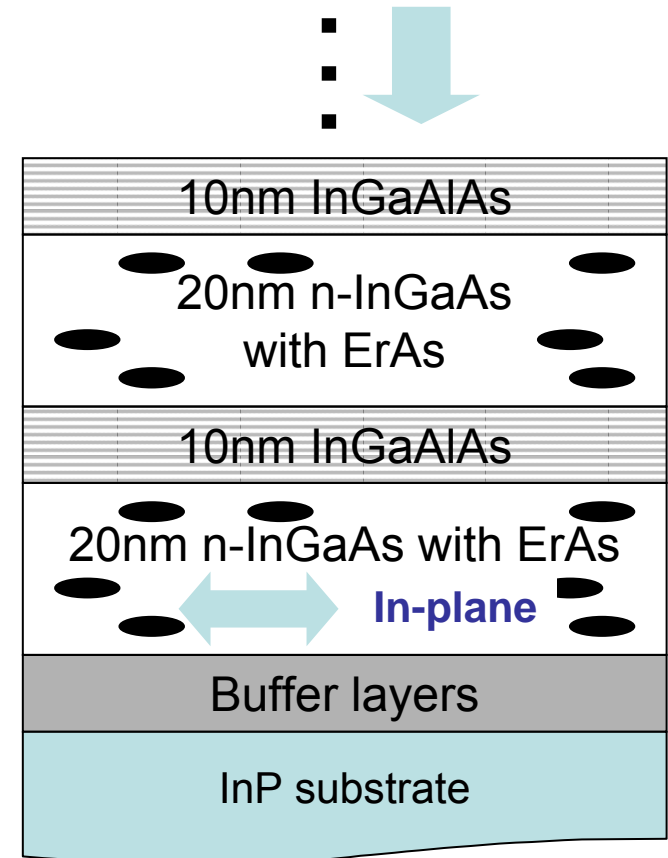
Semi-metal Nanoparticles ➤ Reduce thermal conductivity while improving slightly electrical properties ➤ ZT x2

0.3% ErAs in InGaAs/InGaAlAs Superlattices

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Cross-plane (with filtering)

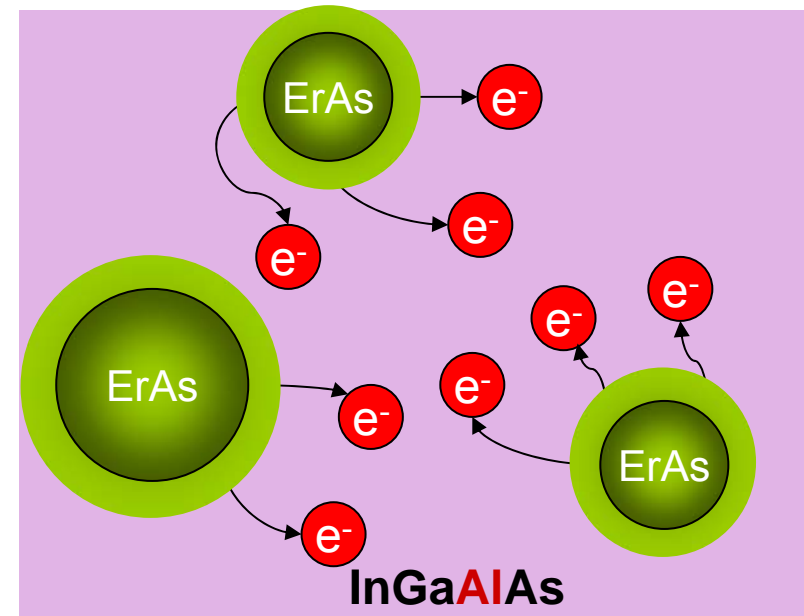
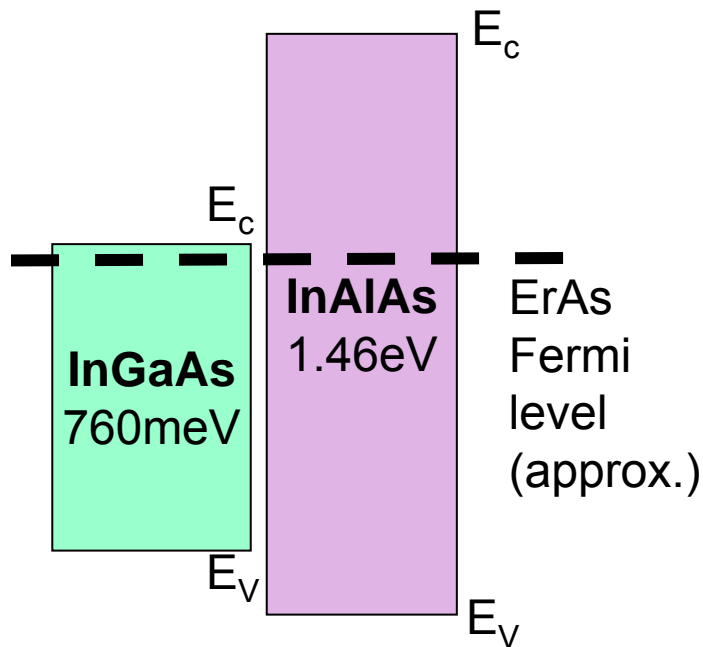


Energy filtering by inserting InGaAlAs layers inside ErAs:InGaAs can enhance cross-plane Seebeck by a factor of 3

Metal nanoparticles

- enhance electrical conductivity
- reduce thermal conductivity
- increase Seebeck coefficient

$$Z = \frac{(\text{Seebeck})^2 (\text{electrical conductivity})}{(\text{thermal conductivity})}$$

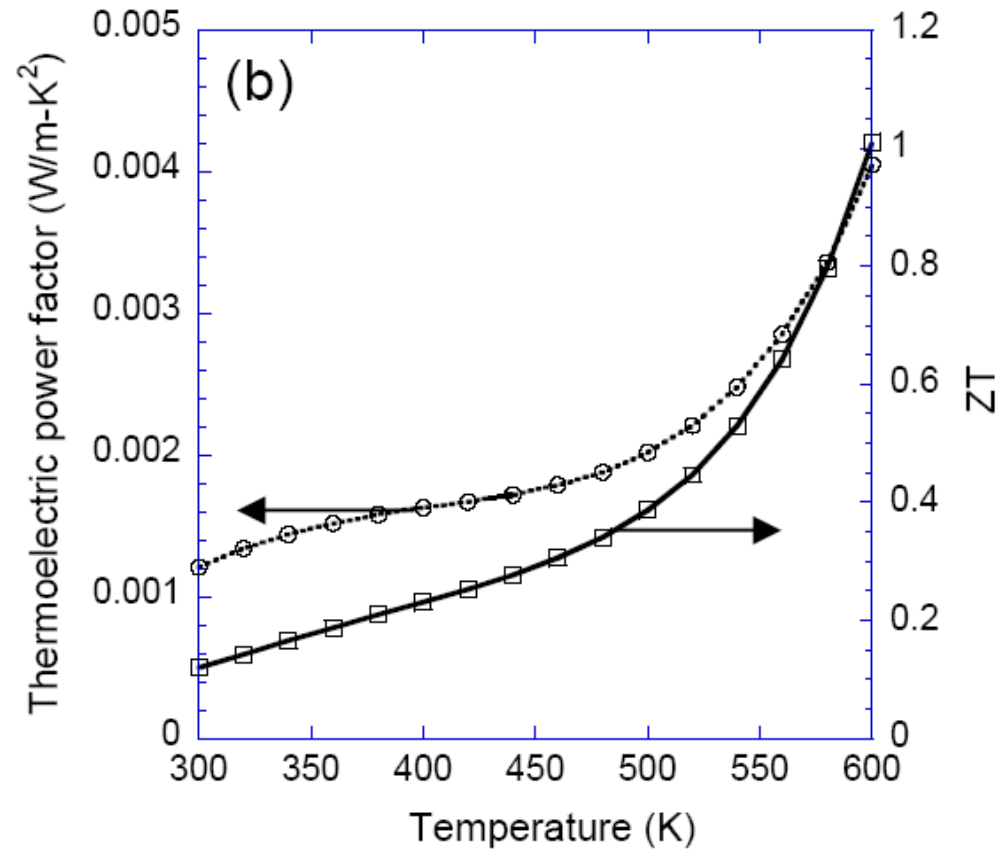
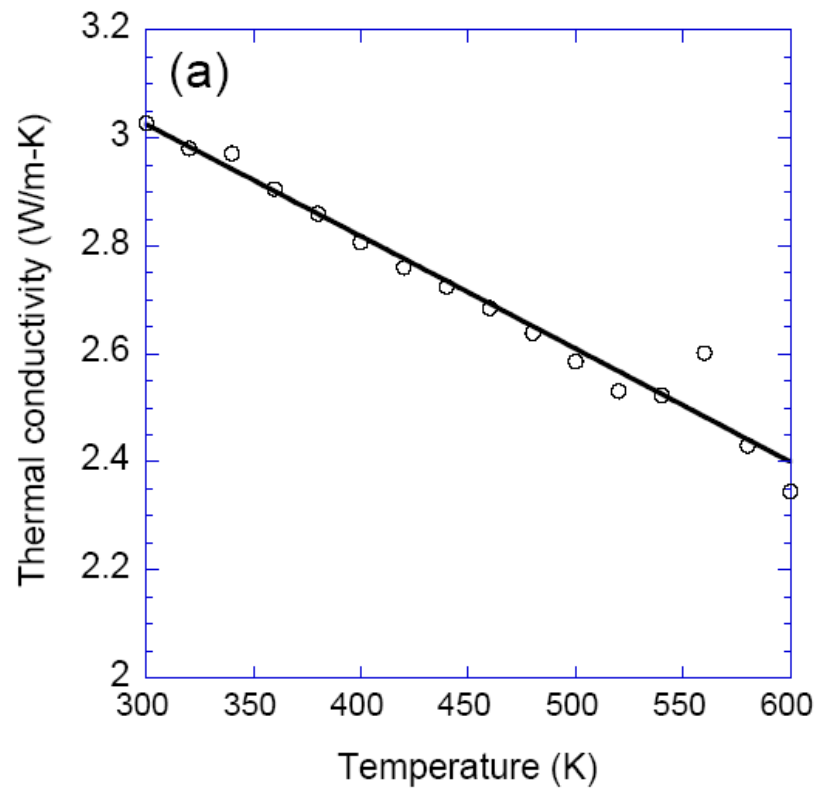


ErAs:InGaAlAs –High Temperature Results

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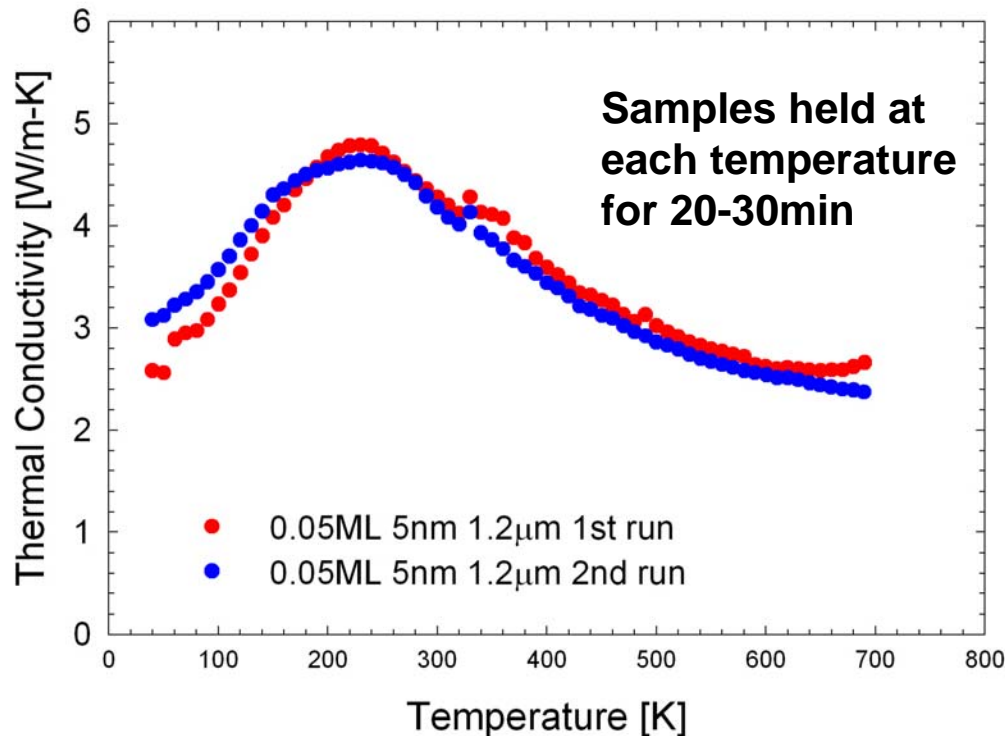
ErAs : InGaAlAs

(0.3%) : (20% InAlAs)

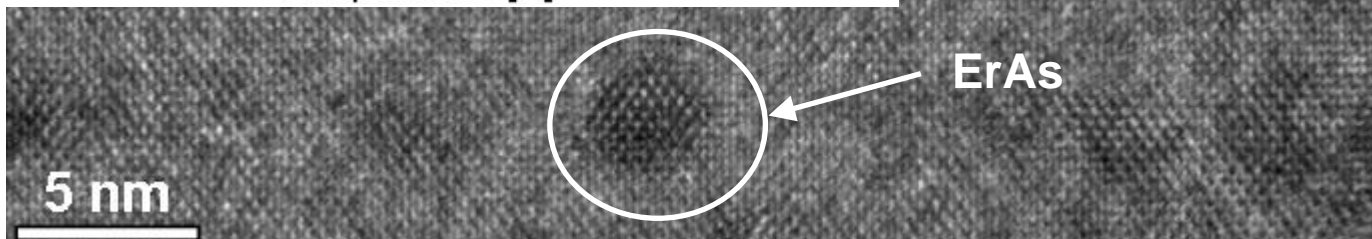
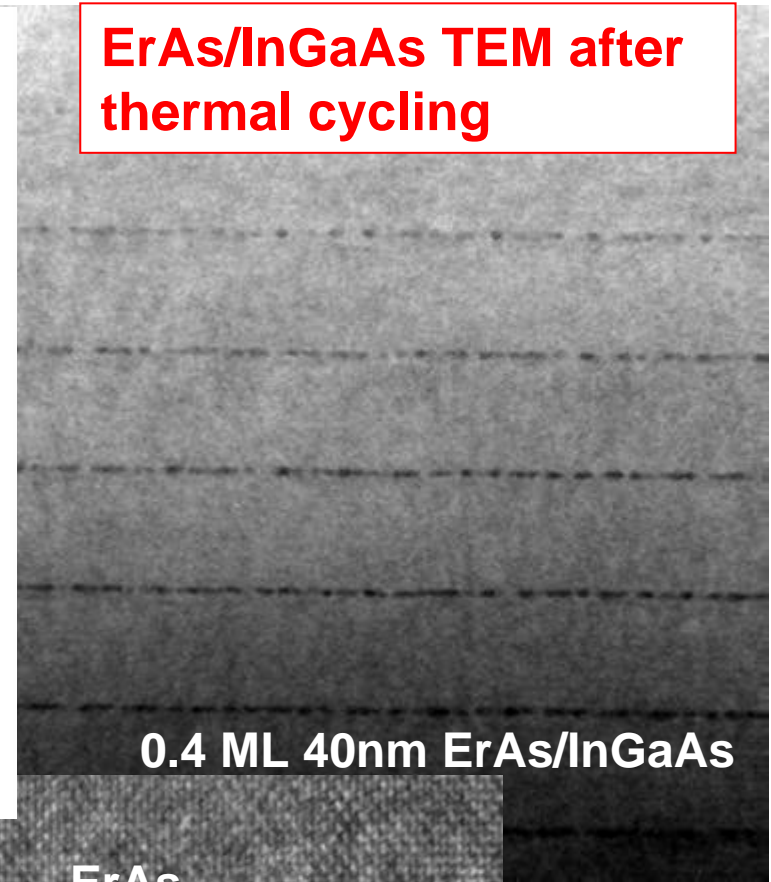


High Temperature Stability of Nanostructures

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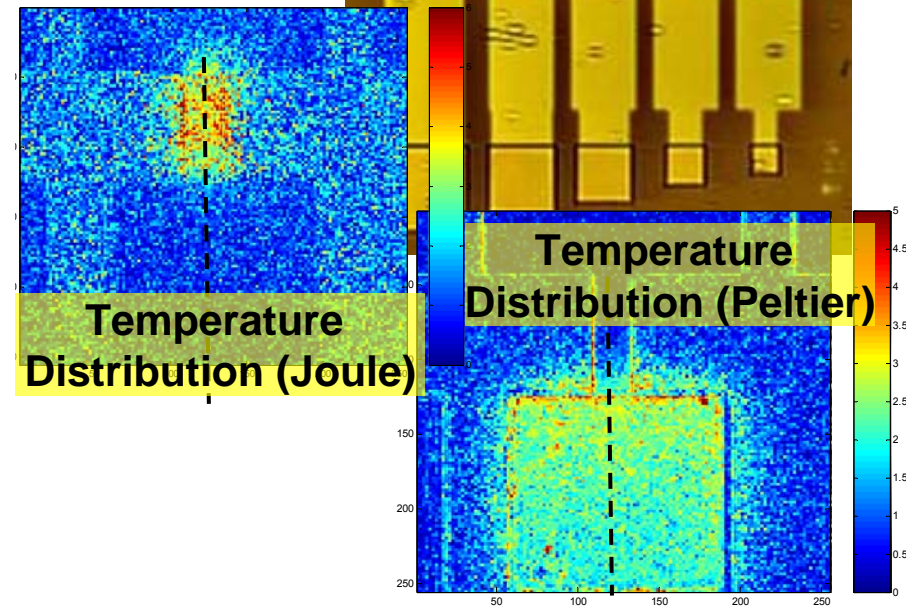
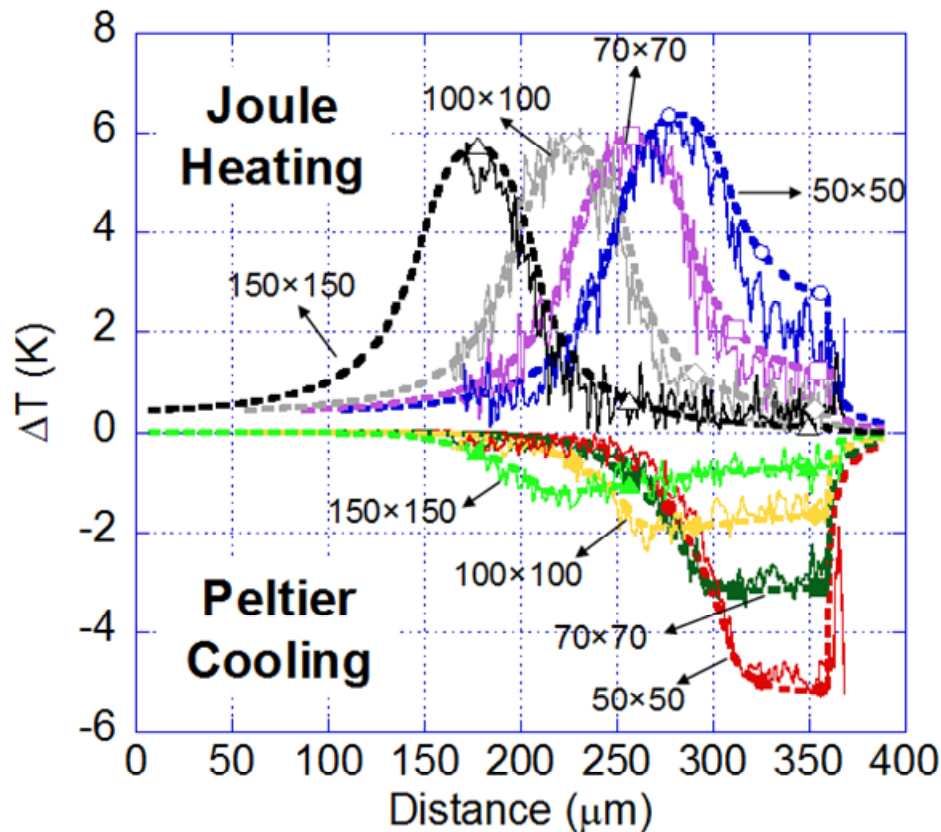
ErAs/InGaAs TEM after thermal cycling



ErAs nanoparticles still visible in TEM after two cycles to 700K. No change in thermal conductivity

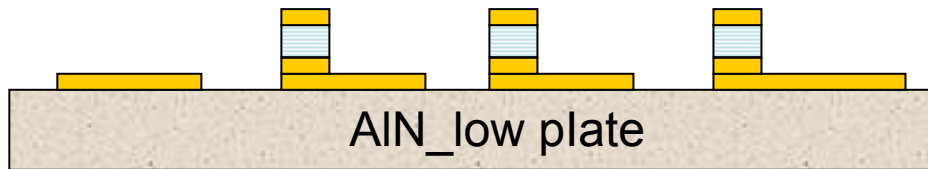
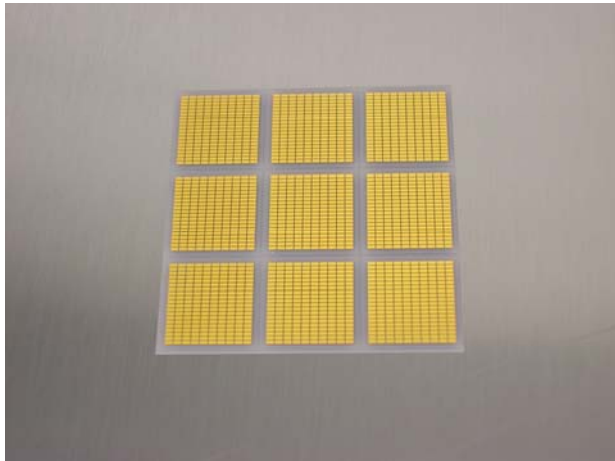
Extraction of Thin-film ZT

	$S(\mu\text{V/K})$	$\sigma(1/\Omega\text{cm})$	$K(\text{W/mK})$
In-plane data	-224	348	N/A
Cross-plane	-233	347	3 (3 ω), 5
Finite Element	-220	330	5

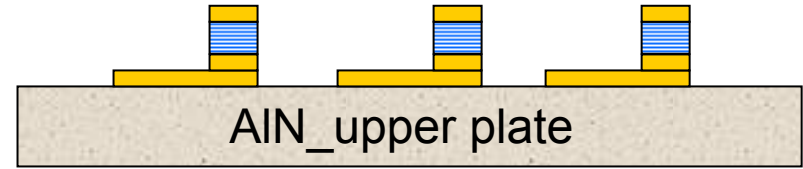
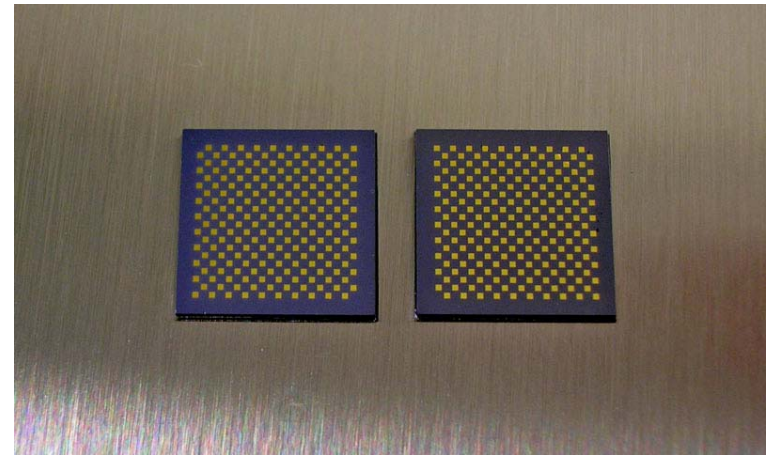


Single element microrefrigerator used to extract **all thermoelectric** properties of 20 μm films

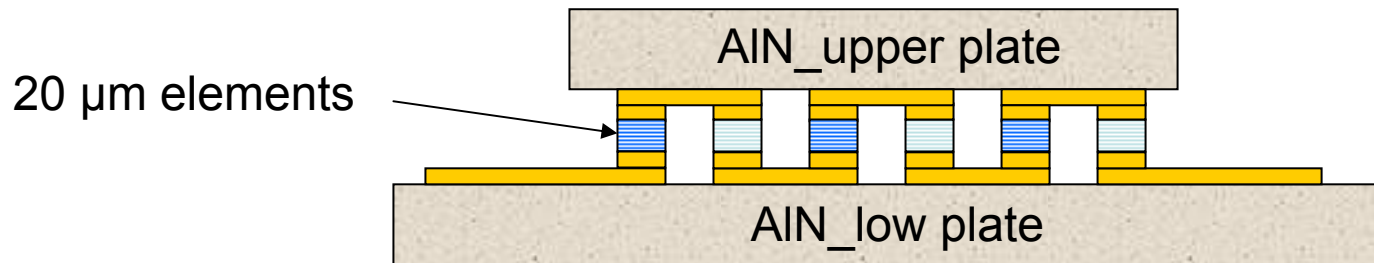
Wafer scale module fabrication



200 elements of p-ErAs array

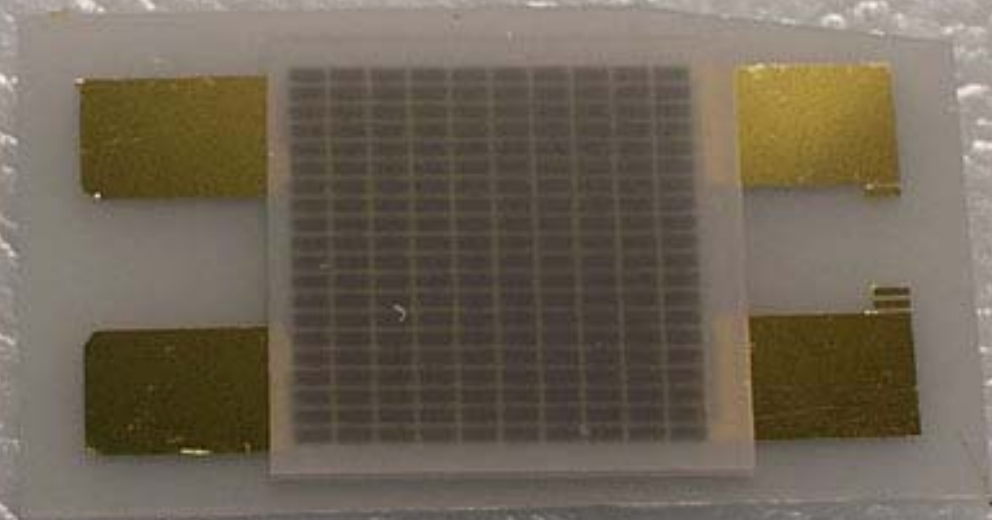


200 elements of n-ErAs array



400 element generator

Module Fabrication

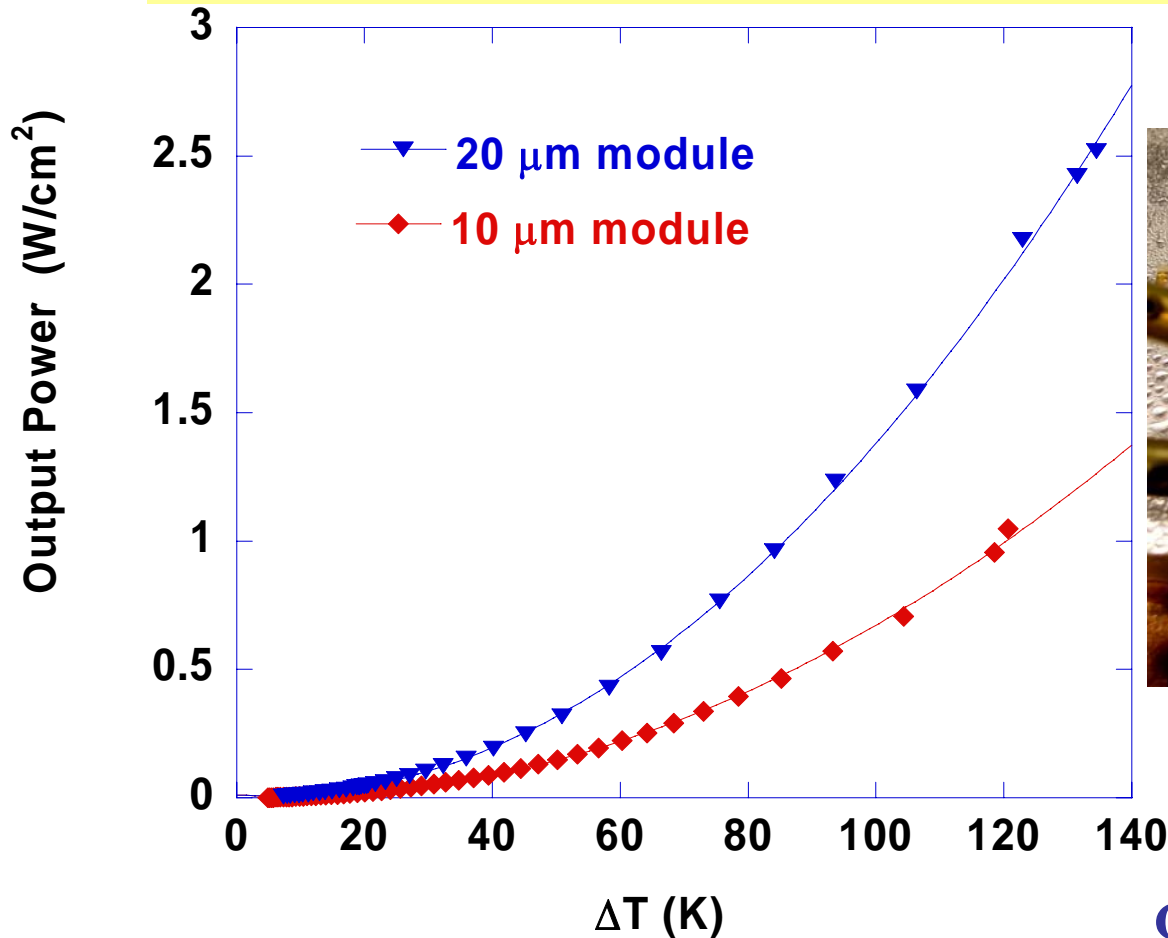


400 element ErAs:InGaAlAs thin film generator

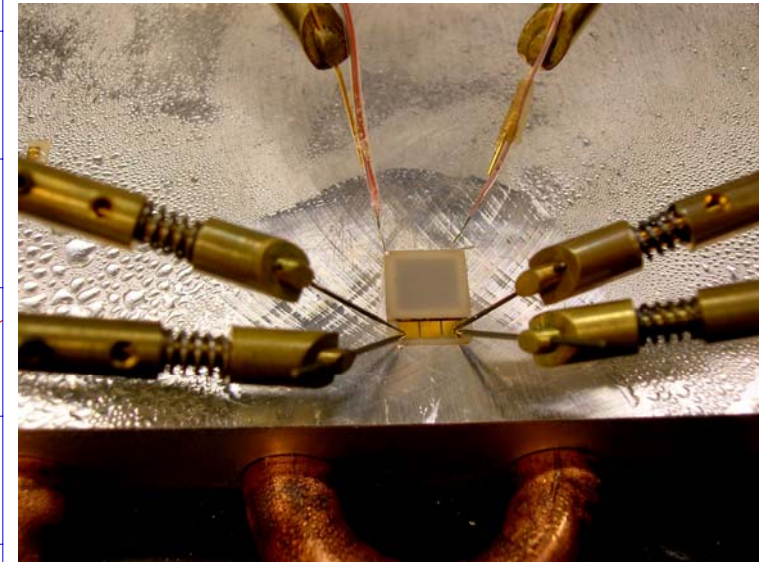
Gehong Zeng, John Bowers (UCSB)

Module Power generation results

400 elements (10-20 microns ErAs:InGaAlAs thin films, $120 \times 120 \mu\text{m}^2$)



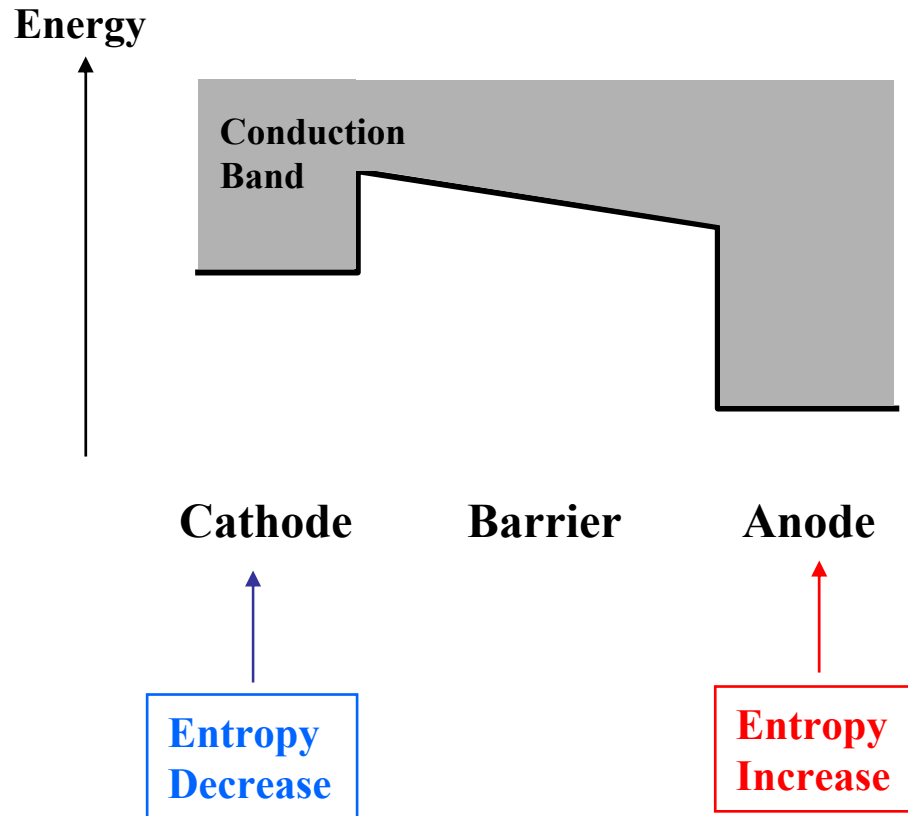
140 μm/140 μm AlN



G. Zeng, J. Bowers, et al.
(UCSB, UCSC) Appl. Physics
Letters 2006

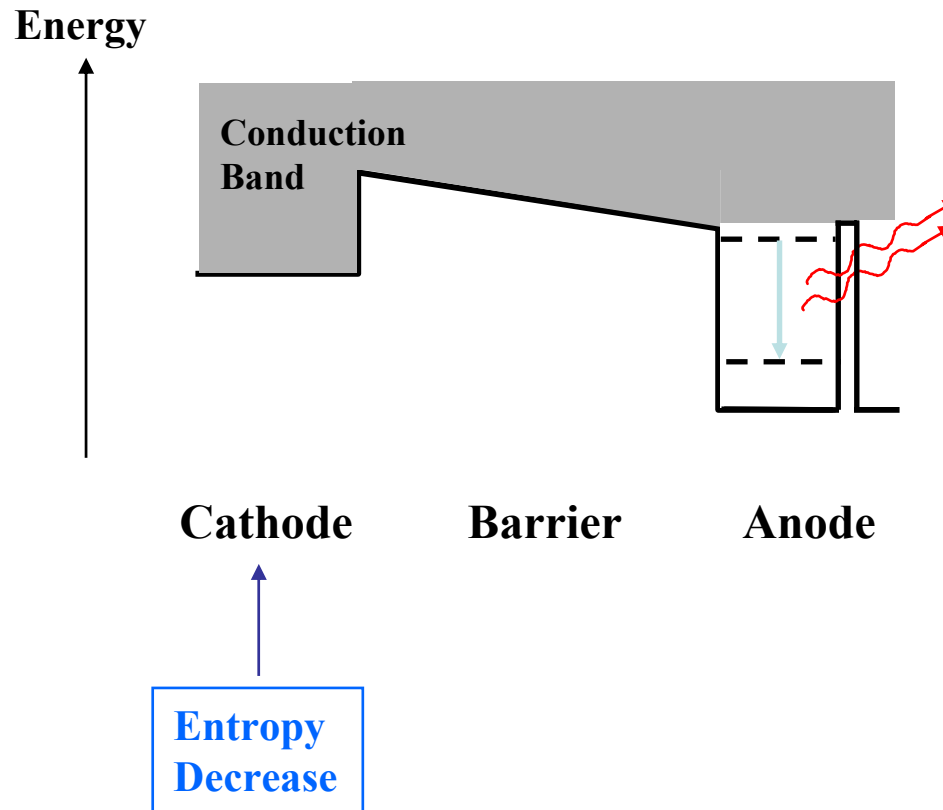
Miniature Refrigerator

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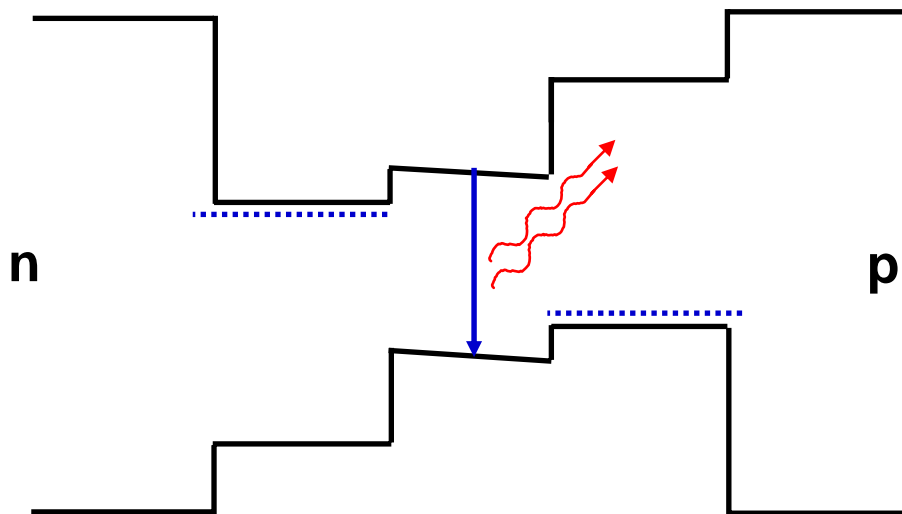
Second Law of Thermodynamics?

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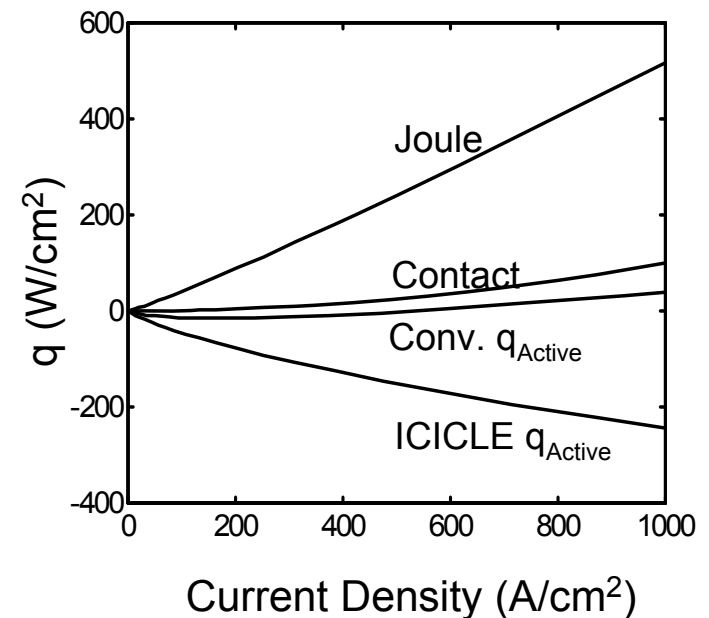
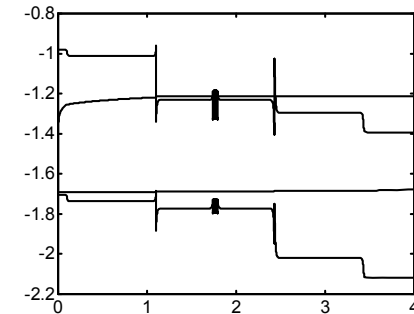
Injection Current Internally Cooled Light Emitter

AS 4/28/2008



Electrically pumped
“optical refrigeration”

GaSb/GaInAsSb.



Summary

- Micro Refrigerators on a Chip (Si, III-V)
 - Localized cooling 10 –150 μm , Cooling power density > 500 W/cm²
- Thermoreflectance Imaging
 - Visible, near IR (sub microns, 0.006K, 1 μs)
- Thermal Runaway in Electro absorption Modulators
- Direct Thermal to Electric Energy Conversion
 - Metal/semiconductor nanocomposites for improved solid-state thermionic energy conversion.
- Opto Thermo Electronic Optimization Devices
 - Internal cooling of semiconductor lasers

x500 0040 25kV 100 μm

Acknowledgement: ONR MURI, DARPA Heretic, Packard Foundation, NSF

Question & Answer

AS 4/28/2008